

Research at high Altitude on Distributed Irradiance Aboard an iNexpensive Cubesat Experiment Critical Design Review

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Team Members: Brandon Antoniak, Alec Fiala, Jeremy Muesing, James Pavek





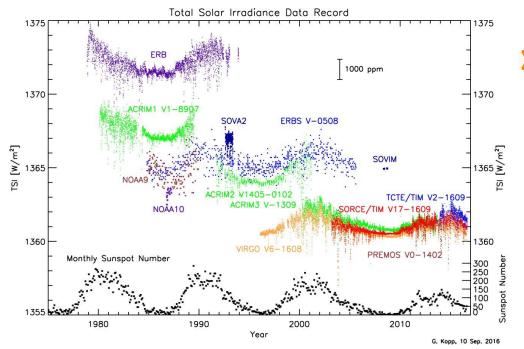
Outline



Project Overview	Jenny, David	5%
Design Solution	Lance	10%
Critical Project Elements	Lance	5%
Detailed Analysis	Jenny, Katie, David, Russell	30%
Risks	David	10%
Verification and Validation	Katie, Russell	20%
Remaining Work	Jenny	20%



Project Motivation



Are these variations real? How does it inform climate science?

Solar irradiance data is plentiful, but...

- The record has gaps
- Datasets vary between different instruments
- Full-scale space missions are costly
- Full-scale space missions are timeconsuming



Project Description



Mission Statement

RADIANCE is a 3U CubeSat-style payload that will collect solar irradiance data, images, attitude information, and ambient atmospheric data during a 2-week circumpolar high-altitude balloon flight.

The mission will launch from Antarctica between November 2017 and February 2018.

• Project Statement

RADIANCE will design, build, test, and deliver a 3U CubeSat-style payload to collect solar irradiance data, images, attitude information, and ambient atmospheric data on a high-altitude balloon flight.



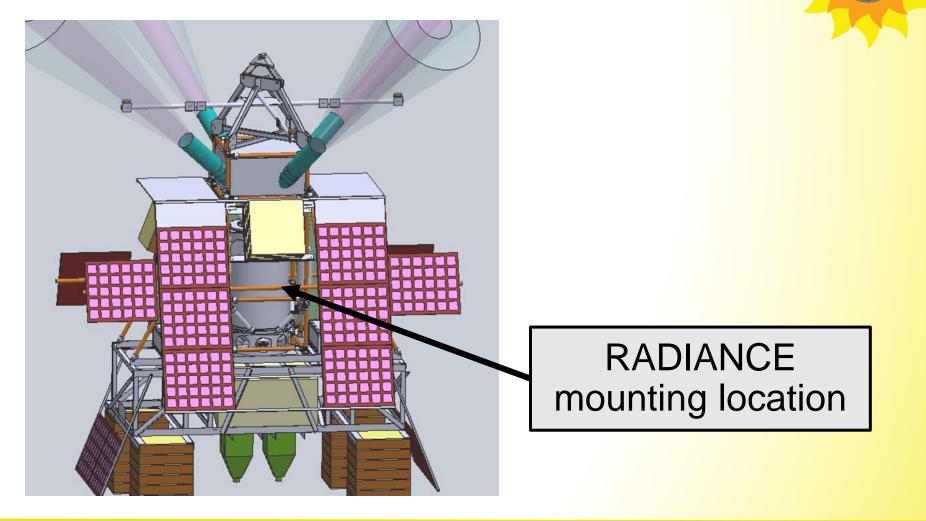
HiWind Gondola & Flight



Mission:
Ground: 8
hours
Ascent: 2 hours
Flight: 2 weeks
Descent: 1 hour



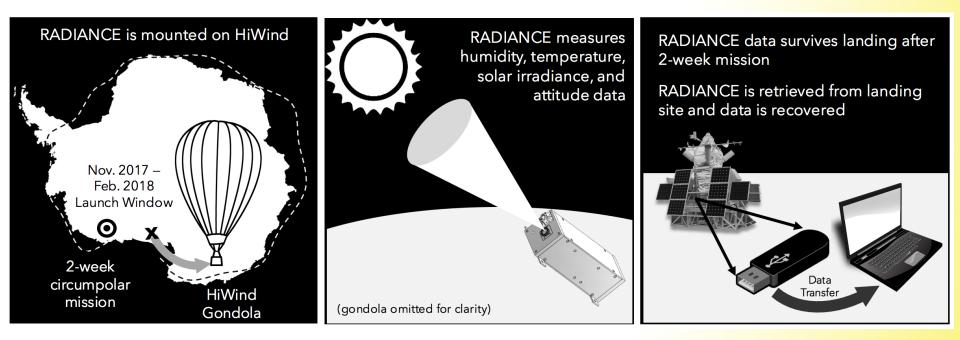
HiWind Gondola & Flight





Mission-Level ConOps







Project-Level ConOps

Critical

Project

Elements

Project

Overview

Design

Solution



Verification

Validation

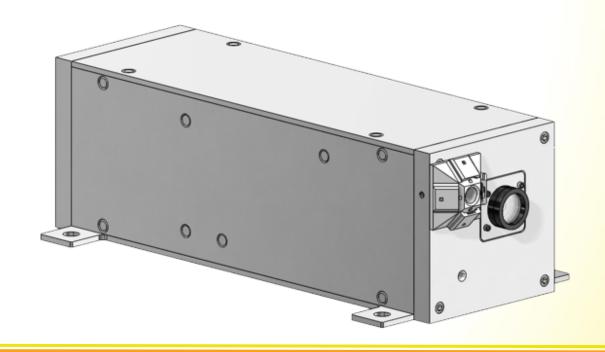
Remainin

g Work

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Power Up

Using external power source equivalent to 15 W of expected HiWind power



Analysis

Risks

Functional Requirements



RADIANCE shall...

- FR1: Take solar irradiance measurements.
- FR2: Survive the environmental conditions of a highaltitude balloon flight up to 40 km.
- FR3: Return data.
- FR4: Determine its attitude.
- FR5: Interface with the HiWind Gondola.
- FR6: Capture images of the Sun in the visible spectrum.

The project deliverables shall include a Path-to-Space report.



Changes Since PDR



Item	Level Achieved	Original Requirement	Design Solution	OK?
Spectrometer	2	Resolution= 1.0 nm Range = 250—1000 nm	Resolution = 1.4 nm Range = 200–1100 nm	\checkmark
Camera	3	$FOV = 5^{\circ} \pm 1^{\circ}$	FOV = 6.32°	\checkmark
Sensors	3	Take environmental data	Descope pressure sensor	\checkmark
Data	3	Data is recoverable	3 drives to protect against radiation	\checkmark
EPDS	1	Independent power	Descope solar panels, use HiWind power	\checkmark
ADS	1	Sub-arcminute accuracy	±1 arcminute accuracy	\checkmark
Structures	2	Volume: 30x10x10cm ³	Volume: 31.81x10x10cm ³	\checkmark

Project Overview Design

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Analysis SRisks

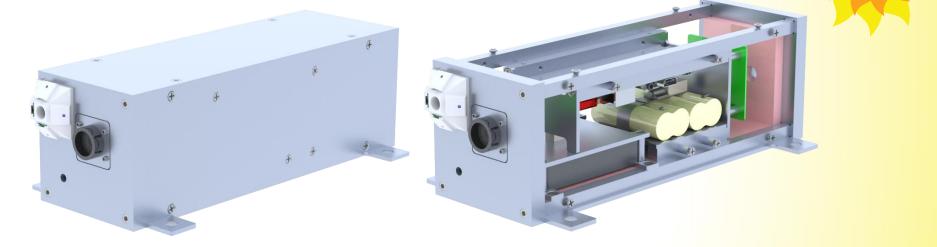
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Design Solution



Overall System Description



Parameter	Overall Values	Req.	OK?
Dimensions	31.81 x 10 x 10 cm ³	DR5.1	\checkmark
Mass	$3.0 \pm 0.2 \text{ kg}$		\checkmark
Power	5.2 to 19.6 W usage, 7.7 W average at cruise		\checkmark
Thermal	-3 to 30 °C internally, spot-heated in critical places		\checkmark
Materials Aluminum 6061, Photopolymer Resin, Polyurethane Foam		DR3.2	~
Project Design Critical Overview Solution Project Analysis Risks Verification Remainin Elements Validation g Work 12			

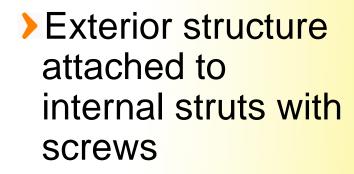
Complete Assembly





6

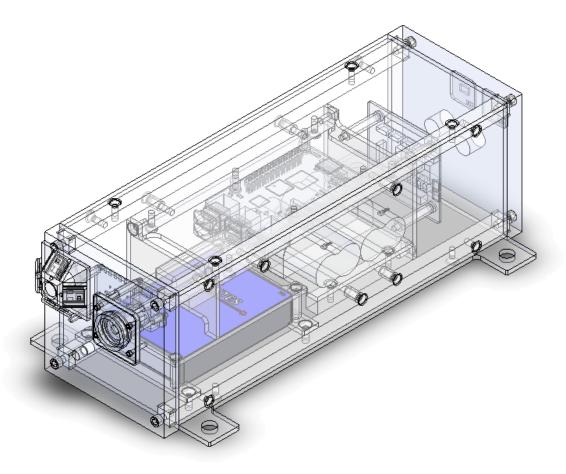




Attachment points to HiWind

Project Design Critical Overview Solution Project Elements Analysis Risks Verification & Remainin Validation g Work 14

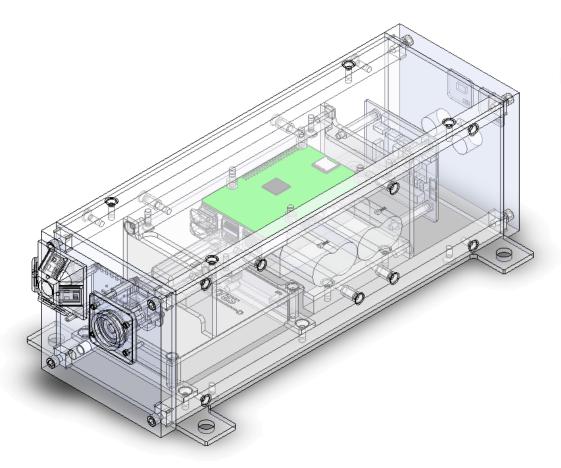
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Avantes fiber optic cable and spectrometer

	Requiremen t	Solution
Resolution	1.4 nm	1.4 nm
Wavelengt h	250-1000 nm	200-1100 nm
Cost	~\$3000	\$2946
Size	Must fit	90x68x20 mm
Power	< 3W	1.25 W
Interface	RPi required	RPi capable

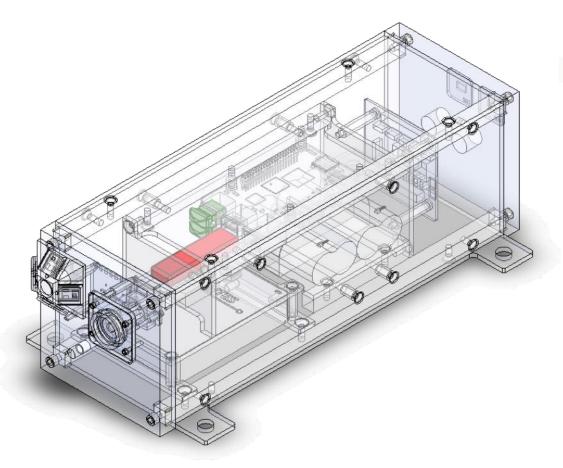




Raspberry Pi microcontroller

	Requiremen t	Solution
Size	Must fit	85x56x17 mm
Cost	<\$100	\$36
Versatility	High	COTS
Interface	RPi needed	RPi capable

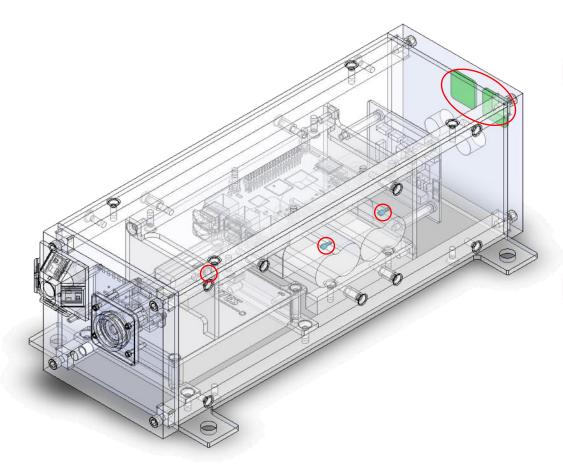






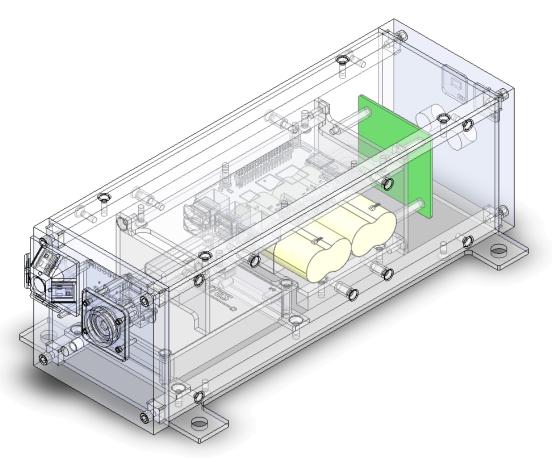
- Three USB storage devices:
 - 1 single-level cell (SLC) drive
 - 2 multi-level cell (MLC) drives





- External sensors (temperature, relative humidity) for atmospheric measurements
- Internal temperature sensors for active thermal monitoring



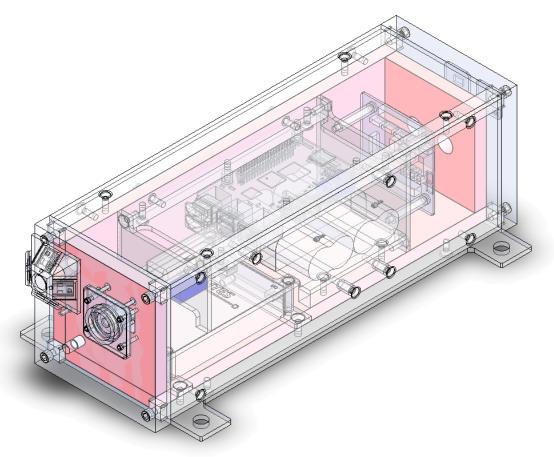




Custom power board for control and distribution

Two Lithium Ion (Liion) batteries

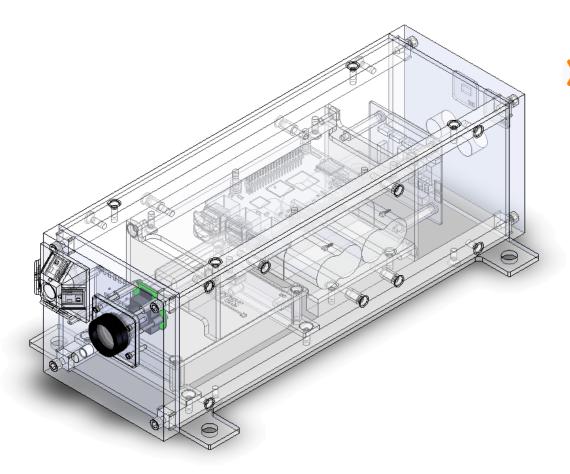






- Polyurethane foam insulation
- Thin film resistive heaters for active thermal control

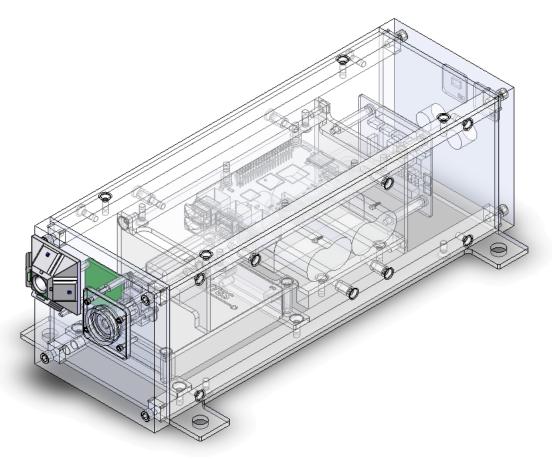






- Camera assembly, including:
 - Raspberry Pi Camera
 - Adjustable focus lens and mounting
 - Double-layer neutral density filter



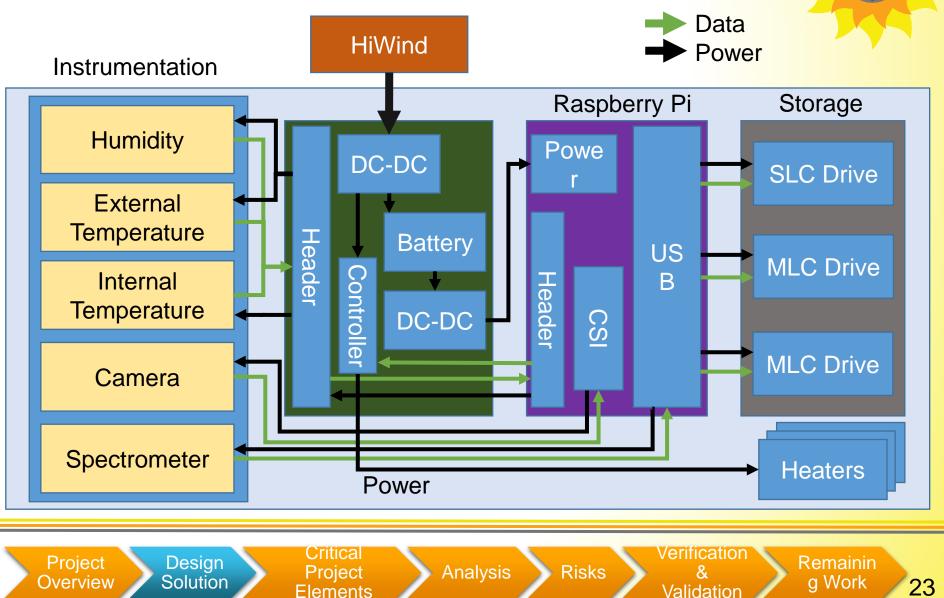


Photodiode array and circuit board for attitude determination

A photodiodes offset at 45° to determine off-sun angle



Functional Block Diagram

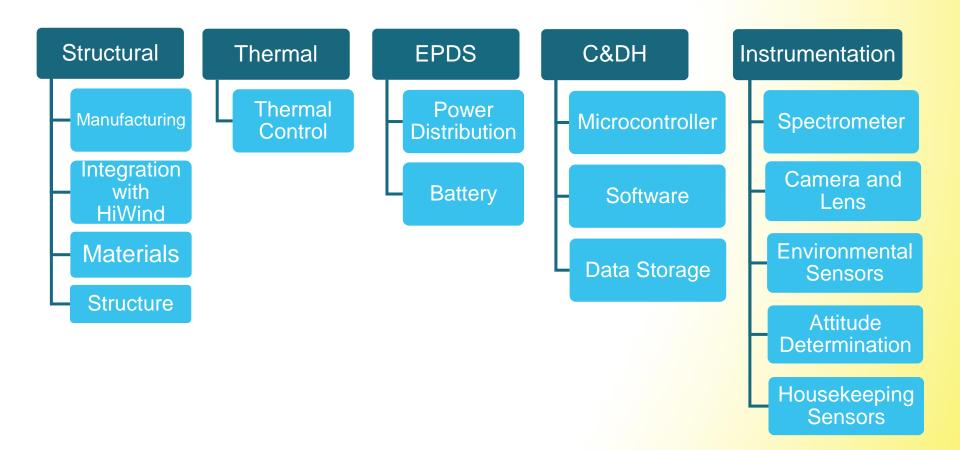




Critical Project Elements

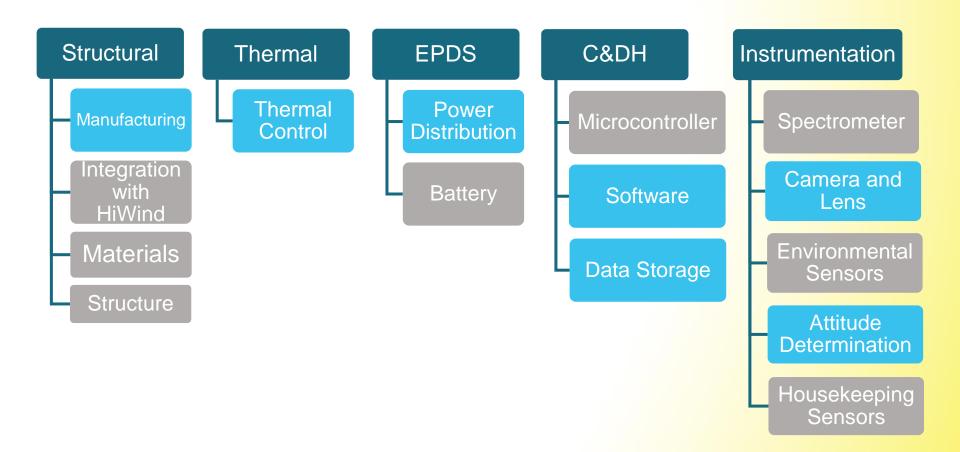


Critical Project Elements





Critical Project Elements





CPE Justification



CPE	Justification	FR
Manufacturing	Some small parts, many components to manufacture	5
Thermal Control	All components must meet thermal requirements	2
Power	Power board design is complex	5
Software	Efficient software design is critical to mission success	3
Data Storage	SEUs are possible, data must survive landing	3
Camera, Lens	Challenging assembly to ensure in-focus images	6
Attitude Determination	Complex design, small parts, challenging hardware/software interface	4

Analysis

Risks

Critical

Project

Elements



Design Solution Remainin g Work

Verification

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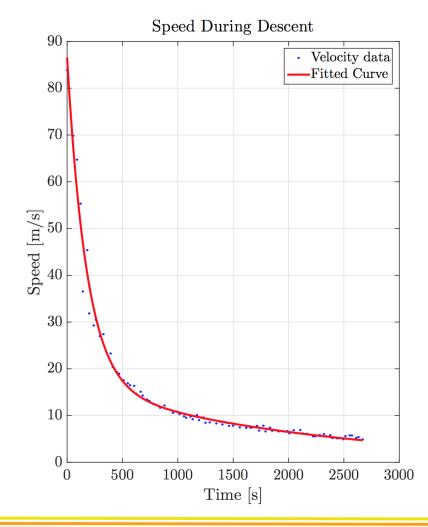
Validation



Design Requirements & Their Satisfaction



Structural Design Motivations



Design

Solution

Critical

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Elements

Analysis

Risks

R3.2: Data storage shall survive landing

- Previous flight data: speed is 5.44 m/s at landing
- Equipped with parachute and crush pads
- Data only taken every ~30 seconds → must infer landing force using ∆ in momentum

Verification

Validatior

Project Overview

g Work

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Remainin

Structural Design

From previous data:

Estimated crash duration:

Fundamental equations:

$$\Delta v = 5.44 \, {
m m \over s}$$

 $m = 2092 \, {
m kg}$

$$t_{\rm impact} = 0.17 \ {
m s}$$

Duration determined
based on height of crush pads and speed

ations:
$$F = \frac{m\Delta v}{t} = \frac{(2092 \text{ kg})(5.44 \frac{\text{m}}{\text{s}})}{0.17 \text{ s}} = 67.75 \text{ kN}$$

 $G = \frac{F}{mg} = 3.30 \text{ Gs}$

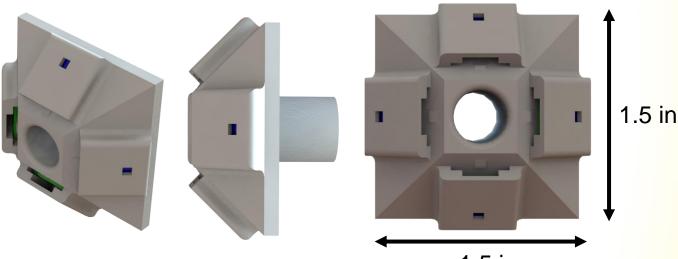
Landing Impact 3.30 Gs



Flash Drive Rating 1500 Gs



Manufacturing Concerns



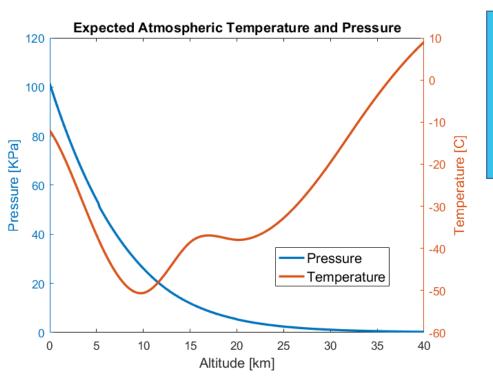
1.5 in

- Some small parts will be 3D printed, 140 µm precision
 - Photopolymer resin is a "low outgassing" material safe to use
- CNC manufacturing tolerance: ± 5 µm
- Foam insulation will be cut with hot wire to ~0.2 cm precision



Thermal Control Motivations





FR2: The system shall survive the environmental conditions of flight

Temperature ranges from -60° to 10° C

Pressure Ranges from 100 kPa to 0.2 kPa



Key Temperatures

Critical components:

Component	Operational Range	Survival Range
Spectrometer	0 to 55 °C	-20 to 55 °C
SLC Flash Drive	0 to 70 °C	-45 to 85 °C
MLC Flash Drive	0 to 60 °C	-10 to 70 °C
Battery	Charge:0 to 45 °CDischarge:-20 to 60 °CStorage:-20 to 50 °C	Charge:0 to 45 °CDischarge:-20 to 60 °CStorage:-20 to 50 °C
Raspberry Pi	-40 to 85 °C	-40 to 85 °C



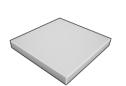
Thermal Control System





>Active Control

- >5W 1D resistive heater on thermostat control
 - Temperature sensors on critical components input to RPi control



Passive Control

- Insulation —slow transient effects during ascent
 - > 3/8" thick insulation
 - Not necessary for cruise (convection is negligible)
- > Radiative coating, $\varepsilon = 0.85$
 - Used to dissipate heat during cruise (negligible in tropopause)



Thermal Model — Assumptions



Radiation

- > Bare aluminum is negligible
- > HiWind has no radiative effect



Convection

Negligible at cruise, exists otherwise

Conduction

- Perfect contact between components
- Components within 3mm are connected thermally
- Thermally isolated from HiWind

Reaches steady state during cruise, on the ground, and in hangar

Powered on the ground



Boundary Conditions

Item	Value
Radiative coating emissivity	$\epsilon = 0.85$
Electronics emissivity	$\epsilon = 0.70$
Insulation emissivity	$\epsilon = 0.30$
Air temperature, ground	260 K (-13.15 °C)
Air temperature, cruise	283 K (9.85 °C)
Air temperature, hangar	298 K (24.85 °C)
External convection, ground	$H = 4.4 \text{ W/m}^{2}\text{K}$
External convection, cruise	$H = 0.002 \text{ W/m}^2\text{K}$

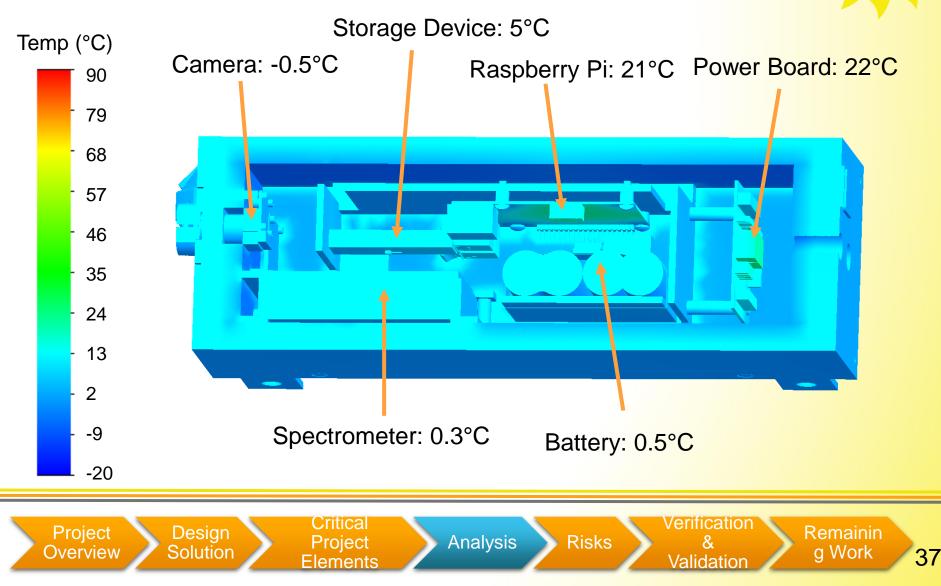


All heating done evenly throughout heating components



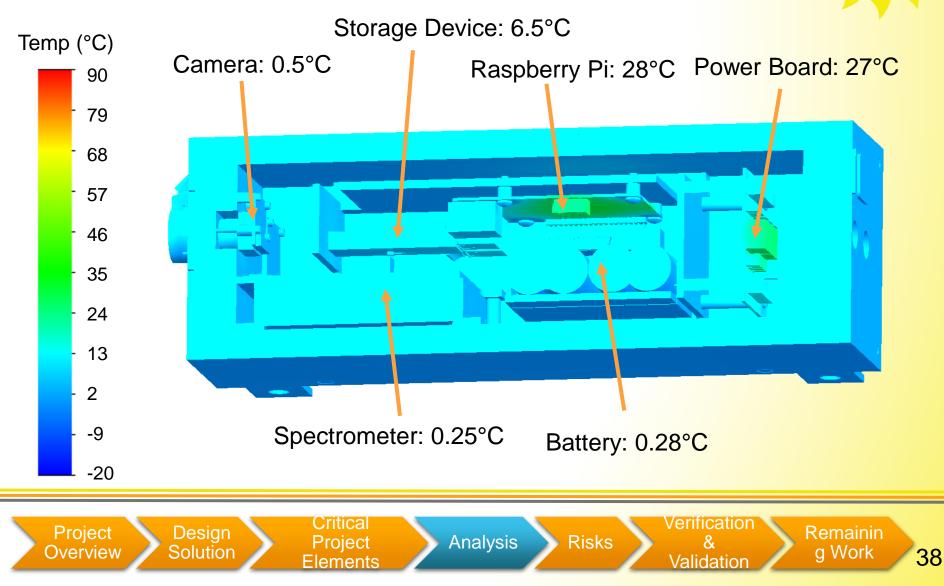
Thermal Analysis

Active control, on the ground, steady state model



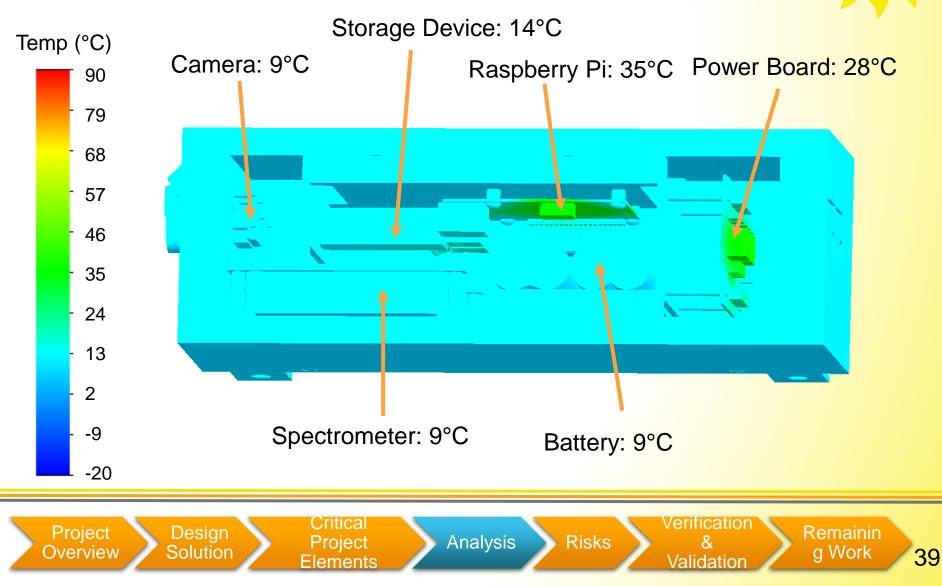
Thermal Analysis

Active control, during ascent, transient model



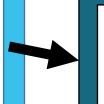
Thermal Analysis

Passive control, during cruise, steady state model



Power Motivation

FR5: The system shall interface with the HiWind gondola



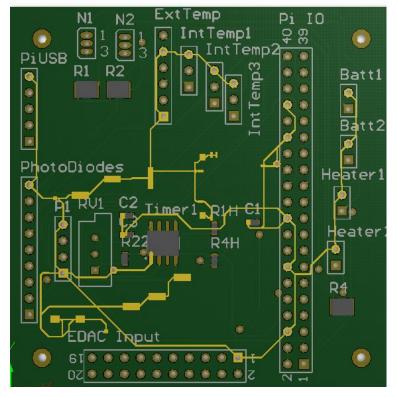
DR5.4: The system shall interface with the HiWind power line

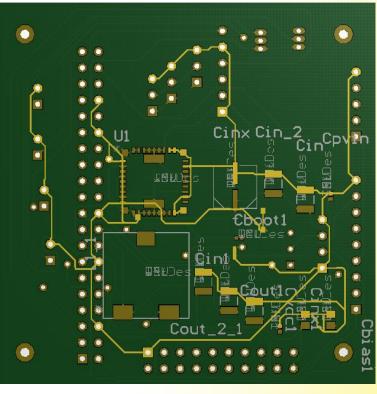
Requiremen t	Description	
5.4.1	System shall not interfere with HiWind	
5.4.2	System shall accommodate a 15W power supply	
5.4.3	System shall accommodate a 26-28V supply	
5.4.4 System shall accommodate an approximately 0.5A supply		
Must distribute power to subsystems		



Power Board Design





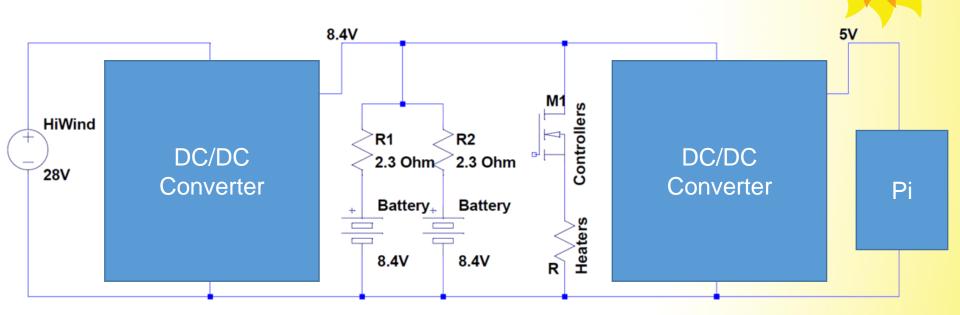




Back



Power Board



8.4V line for batteries and heaters

- Optimal charging and discharging
- Minimize losses
- >5V line required for Raspberry Pi
- Heritage with QB50

Power Budget

(C	

Component	Nominal/Peak Power Draw		
Raspberry Pi	4.25 W	6.7 W	
Spectrometer	1.25 W	1.3 W	
Camera	0.7 W	0.7 W	
Additional Sensors	0.1 W	0.1 W	
Flash Drive (x3)	1.4 W	1.4 W	
Heaters	4.7 W	9.4 W	
Total	12.4 W	19.6 W	
Limits	99.0 W	99.0 W	
Margin	87%	80%	

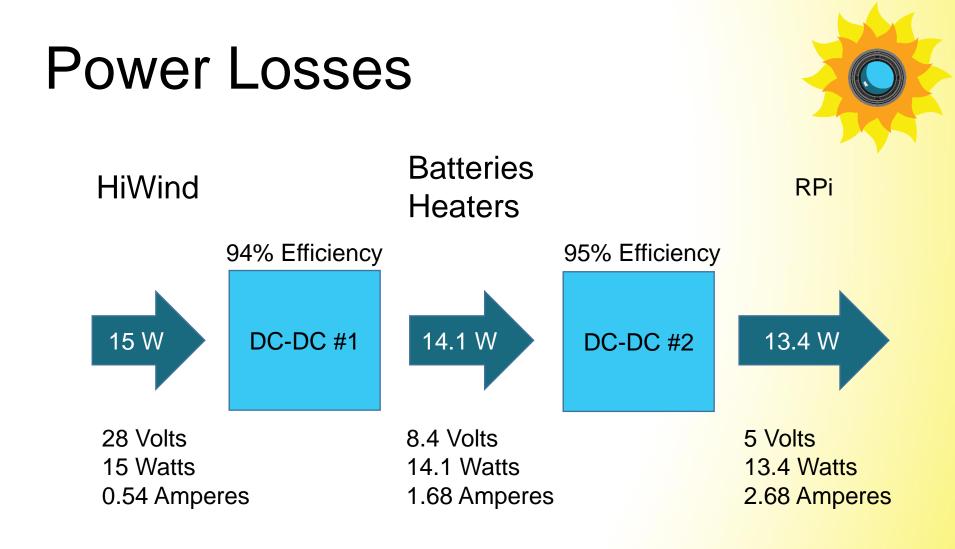
Nominal: Cruise Condition

Sensors, spectrometer, flash drives, microcontroller, and ONE heater

Max Draw: Ascent

 Sensors, spectrometer, flash drives, microcontroller, and TWO heaters







C&DH Motivation



FR3: The system shall return data

Requirement	Description
3.1.1	System shall record science data at least once per minute
3.1.2	Science measurements shall be recorded within 2 seconds of each other
3.1.3	Images shall be recorded once per minute



C&DH Overview



Microcontroller: Raspberry Pi 3 Model B

- High altitude ballooning and CubeSat heritage
- Avantes library interfaces directly
- Simple and robust camera interface
- Safety features
 - Watchdog timer with autonomous reset
 - Current and voltage limitations



Data Storage — SLC Drive



>MX-ES 16 GB SLC Drive

- >14.9 GB available, using 11 GB
- Resistant to radiation/SEUs
- Spectrometer data
 - >10 kB per spectra @ 1 Hz
- Housekeeping, environmental, ADS

Design

Solution

Project

Overview

4 byte or 8 byte measurement @ 1 Hz

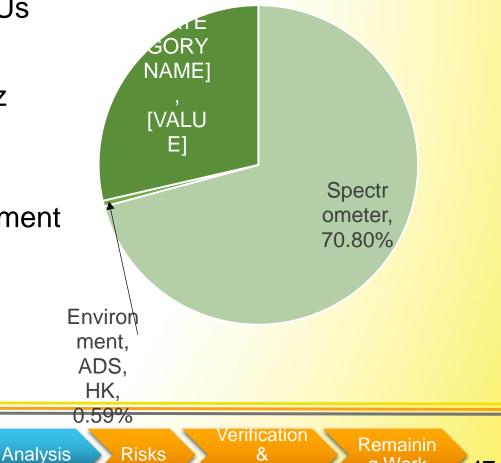
MX-ES

Critical

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Validation

g Work

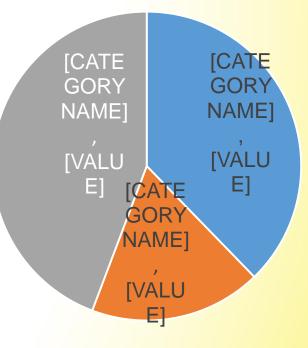
Data Storage — MLC Drives



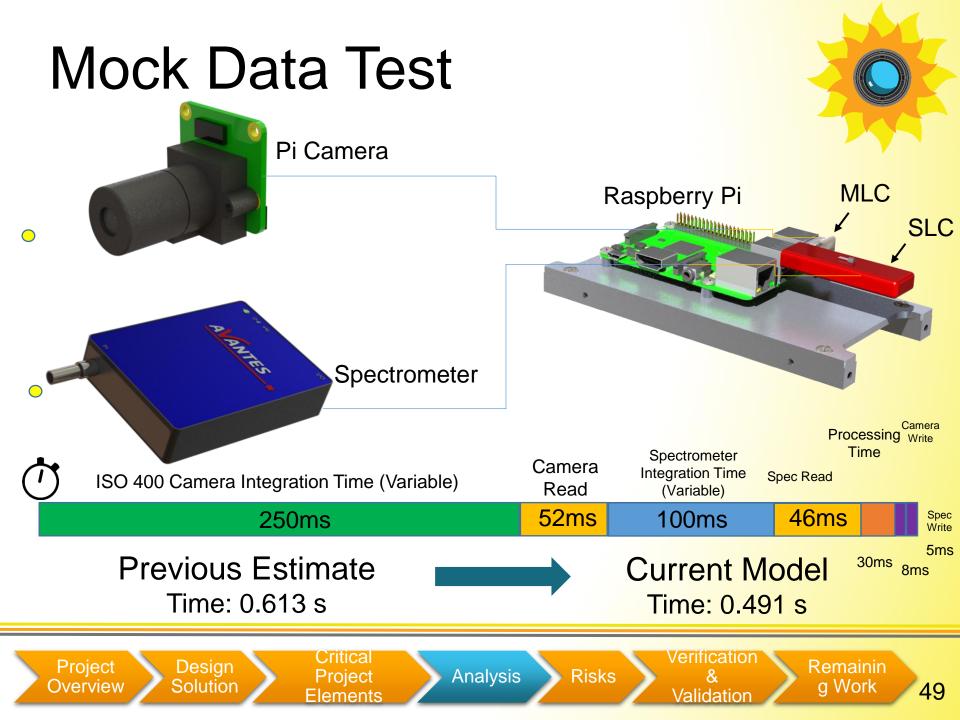
- Samsung Fit MUF-64BB
 - >59.6 GB available
 - Redundant
- Camera images
 - 1.8 MB per image (with safety factor of 2)
 - One image every minute











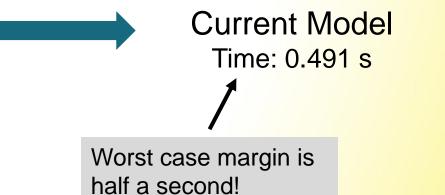
Mock Data Test

Assumptions

- No heating
- No housekeeping/environmental sensors
- Measurement times based on ground data

Test criteria: Inspection of spectrum and images

Previous Estimate Time: 0.613 s



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g Work50

ADS Motivation



FR4: The system shall determine its attitude

Requiremen t	Description	
4.1	Off-sun angle shall be determined within one arc- minute	
4.2	Data shall be recorded synchronously with other data	
Off sun angle needed to corroborate with spectrum data		



Off-Sun Angle Determination

MinXSS heritage

Array of four photodiodes

> Off-set at 45° from each other

Critical

Project

-lements

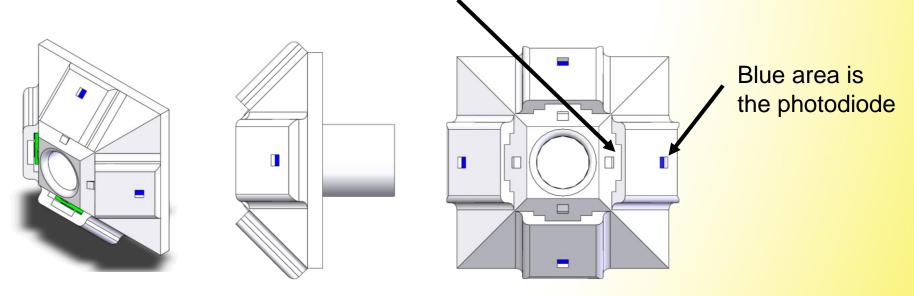
- Circuit board with photodiode slides into array mount
- Square aperture

Design

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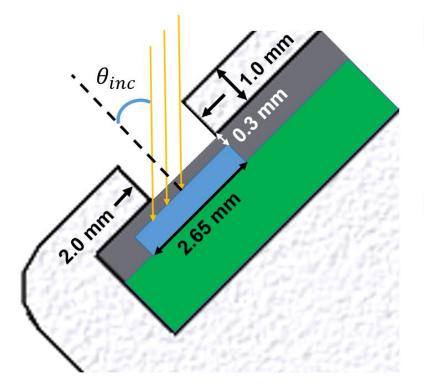
Remainin

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ADS Aperture Motivation





- Active area of PDB-C160SM photodiode proportional to incidence angle
- > At ~59° incidence angle, light "misses" the photodiode \rightarrow 14° FOV

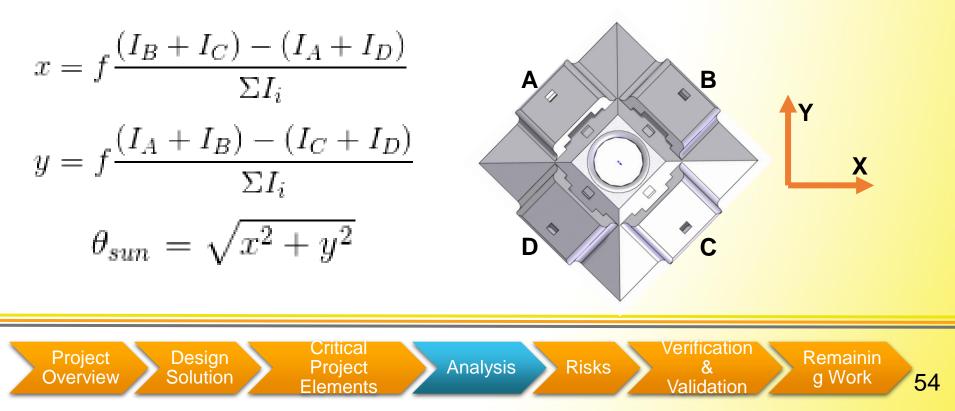


ADS Algorithm



>Utilizing algorithm used by MinXSS

- Component of sun angle in +X and +Y directions computed by relative current in the photodiodes
- Calibration factor f equal to conversion from DN to current divided by field of view (+/- 14°)



Camera Motivation



FR6: The system shall take images of the sun in the visible spectrum

Requirement	Description
6.1	Images shall be stored
6.2	FOV should be $5^{\circ} \pm 3^{\circ}$
6.3	System shall take images once per minute

Camera images provide context for spectrometer data



Camera

Field of View Calculation

Known parameters:

Default FOV = 53.5° h = 2.76 mmSun = 0.5° f = 25 mm

$$FOV = 2\tan^{-1}\left(\frac{h}{2f}\right) = \boxed{6.32^{\circ}}$$

Design

Solution

Camera board Mount

Lens

Project

Overview

Neutral Density Filter Calculation

Flux on Ground = $1050 \frac{W}{m^2}$ Flux at 40 km = $1200 \frac{W}{m^2}$

Using flux and size of the sun on the image sensor, find total power:

Power on Ground: 6.986×10^{-7} W Power at Cruise: 5.721×10^{-5} W

Verification

Validation

 $\frac{6.986 \times 10^{-7} \text{ W}}{5.721 \times 10^{-5} \text{ W}} = \boxed{1.22\%}$

Result:

Choose filter with 96.875% attenuation (OD of 1.5)

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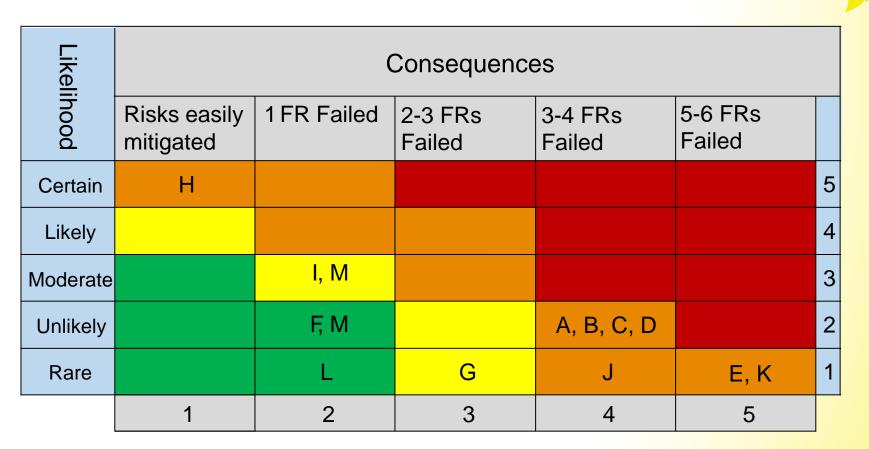




Project Risks



Projects Risk Matrix



8 High Risk Elements

3 Moderate Risk Elements



Project Risks: High Risk

Critical

Project

Elements

	Risk	Likelihood	Consequence	Total	
A	Software Data Write Failure	1	2	8	Journaling
В	Bit Flip	1	2	8	SLC Drive
С	Drive Hardware Failure	2	2	g	Redundant
D	Flash Drive Connection Failure	1	2	8	Drives
E	Overheating	1	5	5	Thermal Model
н	Frost on Optics	5	1	5	Clears in ~48 Hr
К	Pi Software Failure	1	5	5	Watchdog Timer

Analysis

Risks

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Project Risks: Moderate Risk Risk Total Likelihood Consequence High Watt 3 3 G Heater Failure 1 Heaters Automatic Pi **Temporary Power** 3 2 6 Restart Failure Camera Neutral Density С 3 2 0 Oversaturation Filter





Verification & Validation



Verification Plan

Component Selection	Component Testing	Subsystem Testing	Integration Testing	Hard
Datasheets Operational, survival conditions Resolution Completed	Component hardware DAQ Basic breadboard circuits Multimeter Jan 30 - Feb 13	Instruments: ENV/HK Sensors, Camera, Spectrometer C&DH: storage device, Raspberry Pi	All hardware and software integrated FlatSat TVAC Env. Chamber	Testing End Date: Apr 7 Symposium: Apr 21
Feb 13 - Mar 6 Mar 9 - 20 <u>TRR Due</u>				
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Functional Requirements



Take Solar Irradiance Measurements	Spectrometer Calibration
Survive Environmental Conditions	TVAC, Environmental Chamber
Return Data	FlatSat, Datasheet Inspection
Determine Off-Sun Angle	Photodiode Testing
Interface with HiWind	Inspection with ICD
Capture Images of the Sun	Camera Testing

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Functional Requirements



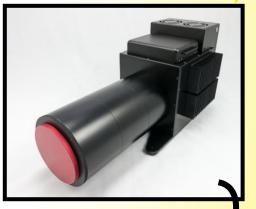
Take Solar Irradiance Measurements	Spectrometer Calibration
Survive Environmental Conditions	TVAC, Environmental Chamber
Return Data	FlatSat, Datasheet Inspection
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Capture Images of the Sun	Camera Testing
Project Design Critical Overview Solution Project Elements	Analysis Risks Verification & Remainin & g Work

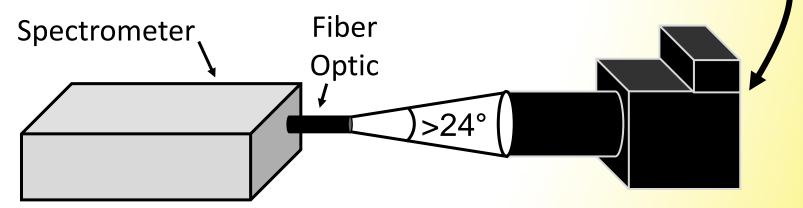
Validation

Spectrometer Calibration

Verify spectrometer readings with known-output source Verification Method: **TEST & ANALYSIS**

> Keo *Alcor* Low-Brightness Source



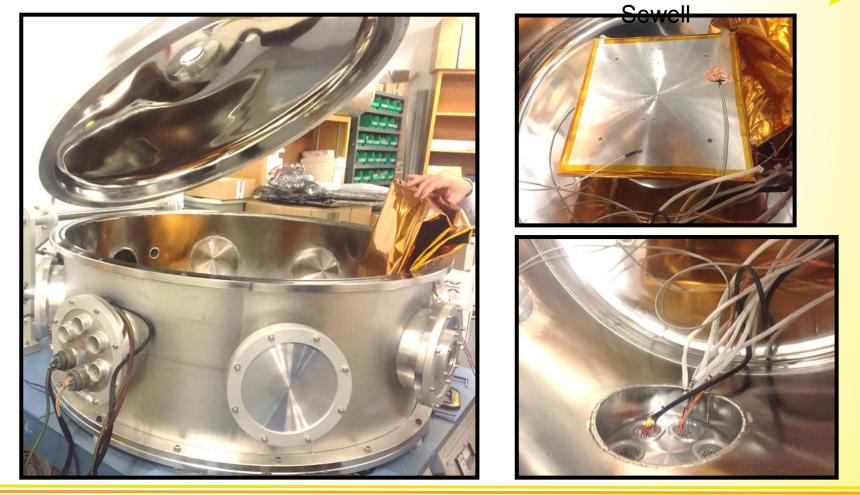


Calibration source provided by Dr. Bob Marshall



TVAC Testing

Validate thermal model at cruise conditions provided by Dr. Scott





Environmental Chamber

Validate thermal model at most extreme ascent conditions



Design

Solution

Russells Temperature Environmental Test Chamber

- Capable of temperatures down to -68°C
- Operates at ambient pressures
- Chamber size: 82 x 127 x 196 cm³

Environmental chamber provided by Dr. James Nabity



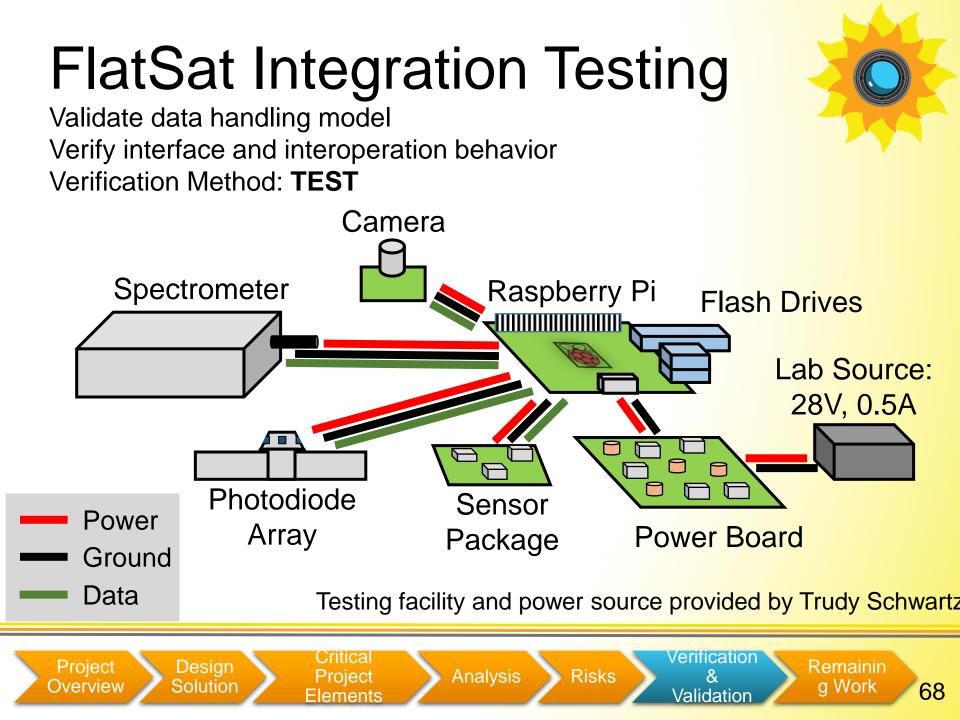
Critical Project Iements

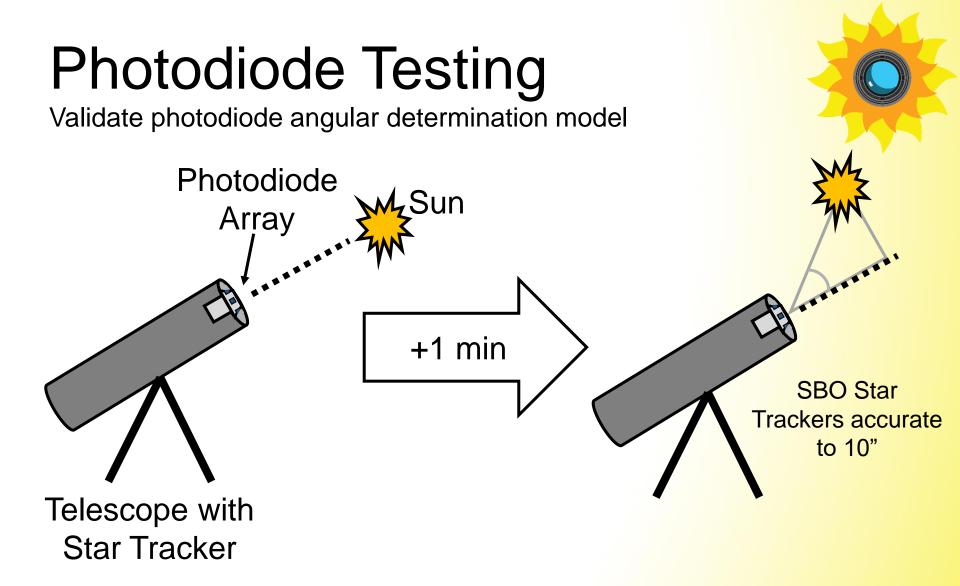
Analysis 📄 Risks

Verification & Validation









Telescope and star-tracking equipment provided by Fabio Mezzalira, SBC



Animation

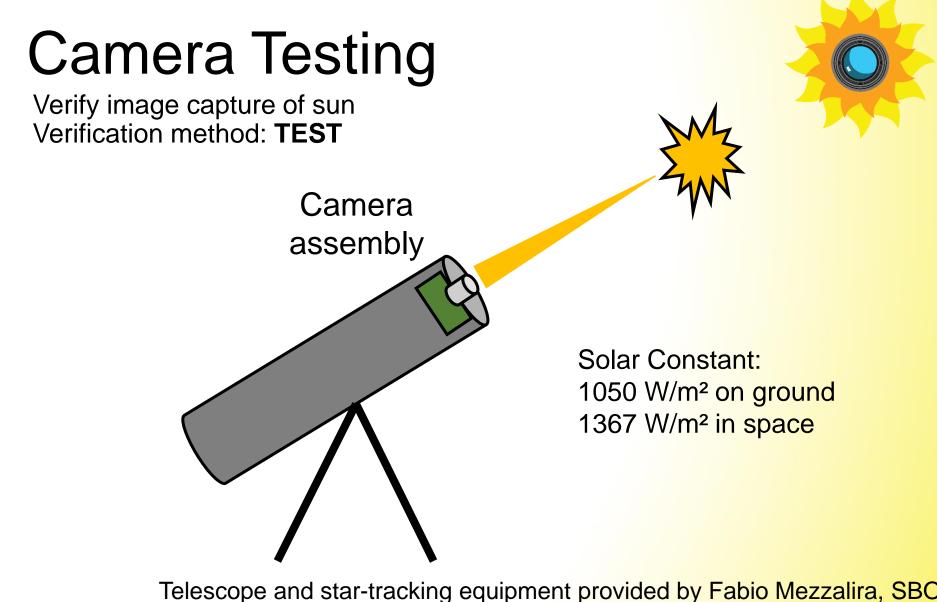


 Angular rate of off-sun angle:

 0.232 arcmin/sec
 0.004 deg/sec

 STK simulation will be run for exact testing dates/times



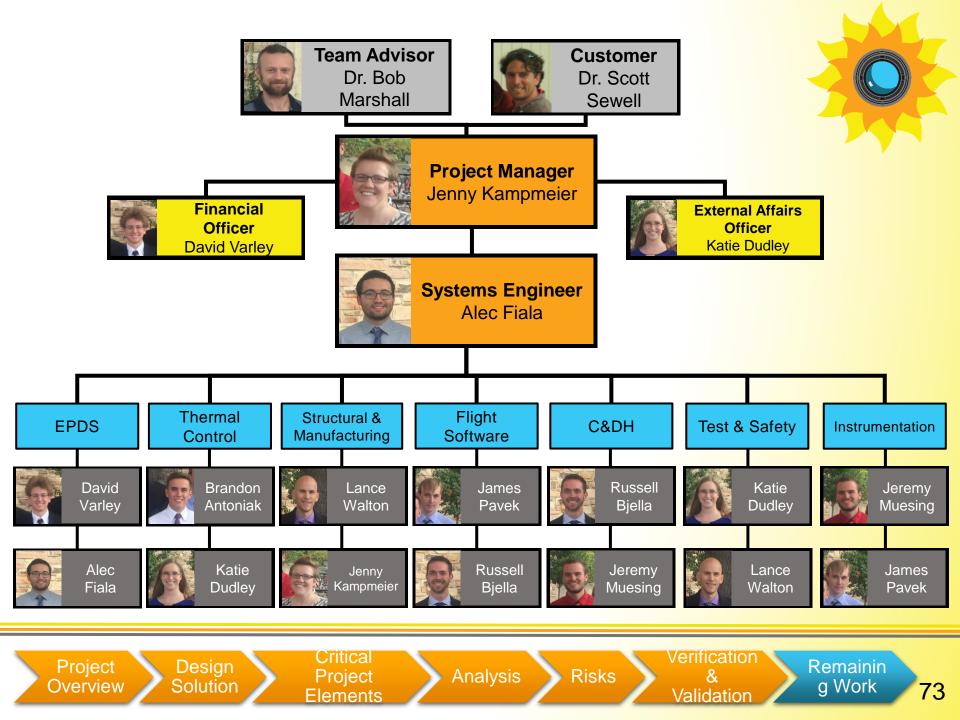






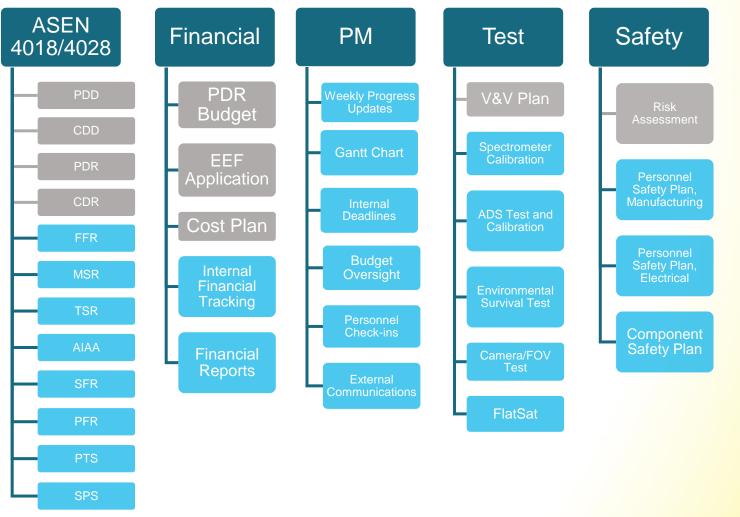
Project Planning & Remaining Work





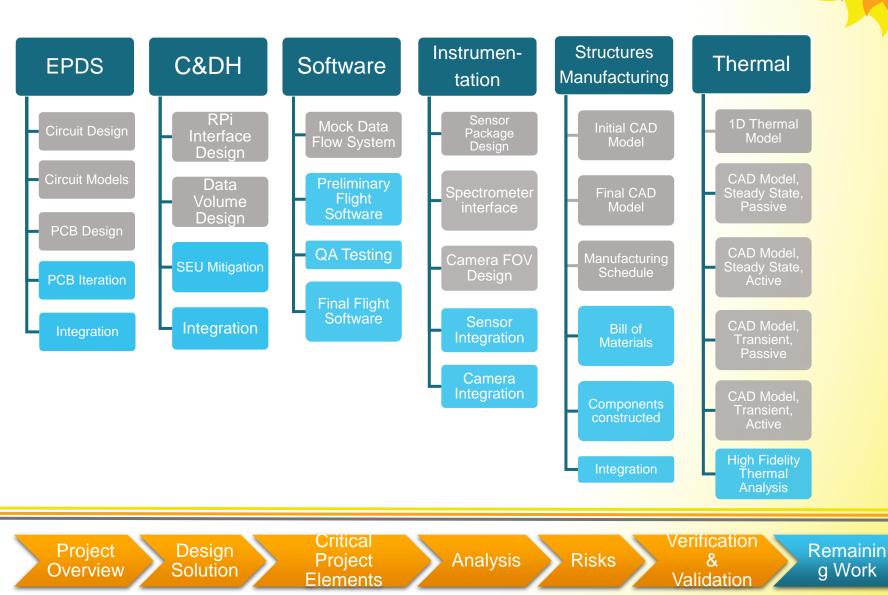
Work Breakdown Structure







Work Breakdown Structure





		0	Task Mode 🔻	Task Name 👻	Duration	✓ Start ✓	Finish 🗸	an 5, 17 3 66 7 W 7 6 5 5 66 1		3 M 1 W	21.0.15	344-25 5 - 60			1 5
	1	~	-3	EEF Proposal	13 days	Tue 10/11/16	Fri 10/28/16								
	9	~	*	▷ CDR	36 days	Mon 10/10/16	Mon 11/28/16								
	36		*	Winter Break	22 days	Fri 12/16/16	Mon 1/16/17								
	37			4 FFR	2 days	Tue 11/29/16	Wed 11/30/16								
	38		*	Create outline	2 days	Tue 11/29/16	Wed 11/30/16								
	39		*?	<new task=""></new>											
	40		-	4 TEST	49 days	Mon 1/30/17	Fri 4/7/17				TE	ST _			
	41		*	Component Testing	11 days	Mon 1/30/17	Sun 2/12/17			Compo	nent Testi	ing 💼		_	
	42		*	Subsystem Testing	16 days	Mon 2/13/17	Sun 3/5/17								
	43		*	Test Status Review	0 days	Mon 3/6/17	Mon 3/6/17								
	44		*	Integration Testing	11 days	Mon 3/6/17	Sun 3/19/17								
	45		*	TVAC	2 days	Wed 3/8/17	Thu 3/9/17								
	46		*	Environmental Chamber	1 day	Tue 3/14/17	Tue 3/14/17								
	47		*	FlatSat	2 days	Sat 3/18/17	Sun 3/19/17								
	48		*	Internal Test Deadline	0 days	Fri 4/7/17	Fri 4/7/17								
	49		m ,	MANUFACTURING	18 days	Tue 1/17/17	Thu 2/9/17	MANUFACTURING		_	-	-		-	
GANTT CHART	50		*	Machine shop training	5 days	Tue 1/17/17	Mon 1/23/17	Machine shop training							
Э	51		*	Top Exterior Plate	1 day	Tue 1/17/17	Tue 1/17/17	Top Exterior Plate							
LIN	52		*	Side Exterior Plates	2 days	Wed 1/18/17	Thu 1/19/17	Side Exterior Plates	in a						
GAI	53		*	Bottom Exterior Plate	1 day	Fri 1/20/17	Fri 1/20/17	Bottom Exterio	or Plate	_					
	54		*	Back Plate	1 day	Mon 1/23/17	Mon 1/23/17		Back Plat	te me					
	55		*	Main Support Bars	2 days	Tue 1/24/17	Wed 1/25/17		Main Support	t Bars 🎽					
	56		*	Front Plate	2 days	Thu 1/26/17	Fri 1/27/17			Front Plate		_			
	57		*	ND Filter Threads	5 days	Mon 1/30/17	Fri 2/3/17			ND F	ilter Three	ads 💼			
	58		*	Photodiode Array	5 days	Mon 1/30/17	Fri 2/3/17			Phot	odiode An	ray 💼			
	59		*	Raspberry Pi Support Bars	1 day	Mon 1/30/17	Mon 1/30/17			Raspberry Pi	Support B	ars 🐂			
	60		*	Battery Support Bars	1 day	Tue 1/31/17	Tue 1/31/17			Batt	tery Suppo	ert Bars	Ě.		
	61		*	Raspberry Pi Plate	1 day	Wed 2/1/17	Wed 2/1/17				Raspber	rry Pi Pi	ate 揓		
	62		*	Battery Plate	1 day	Thu 2/2/17	Thu 2/2/17					Batter	y Plate 👔		
	63		*	Flash Drive Plate	1 day	Fri 2/3/17	Fri 2/3/17					Flash	Drive Plat	e 🊈	
	64		*	Power Board Plate	1 day	Mon 2/6/17	Mon 2/6/17						Powe	r Board A	Plate *
	65		*	Spectrometer Top Plate	1 day	Tue 2/7/17	Tue 2/7/17						Spectro	ometer T	op Pla
	66		*	Spectrometer Bottom Plate	2 days	Wed 2/8/17	Thu 2/9/17						Spectr	ometer B	lotton
	67			▲ THERMAL	48 days	Tue 1/17/17	Thu 3/23/17	THERMAL			-			-	
	68		*	High-fidelity thermal models	29 days	Tue 1/17/17	Fri 2/24/17	High-fidelity thermal models			-				
	69		*	Thermal Report	5 days	Sun 3/19/17	Thu 3/23/17								
	70			▲ Software	62 days	Tue 1/17/17	Wed 4/12/17				-			-	
	71		*	Component Code	20 days	Tue 1/17/17	Mon 2/13/17	Component Code						-	
	72		*	Photodiode Algorithm	5 days	Tue 2/14/17	Mon 2/20/17								
	73		*	Data Handling Algorithm	10 days	Tue 2/21/17	Mon 3/6/17								
	74		*	Integrated Software	20 days	Tue 3/7/17	Mon 4/3/17								
	75		*	QA Testing	7 days	Tue 4/4/17	Wed 4/12/17								
	76		-	4 EPDS	28 days	Tue 1/17/17	Thu 2/23/17	EPDS						7	6
	77		*	Power board iterations	21 days	Tue 1/17/17	Tue 2/14/17	Power board iterations							
	78		*	Configure MOSEET	2 days	Mon 1/23/17			Configure MOSFE	T					

Cost Plan



	Cost	Margin	%	
Purchased	\$55	\$0	0%	
Spectrometer	\$2947	\$0	0%	No margin
Components with no Margin	\$119	\$0	0%	required
Remaining Components	\$1446	\$362	25%	
Total	\$4567	\$362	8%	
Total w/ Margin	\$492	9		

Component	Lead Time		
Metal	1 Week		All other
Spectrometer	3 Weeks	$\boldsymbol{\mathcal{S}}$	components are COTS





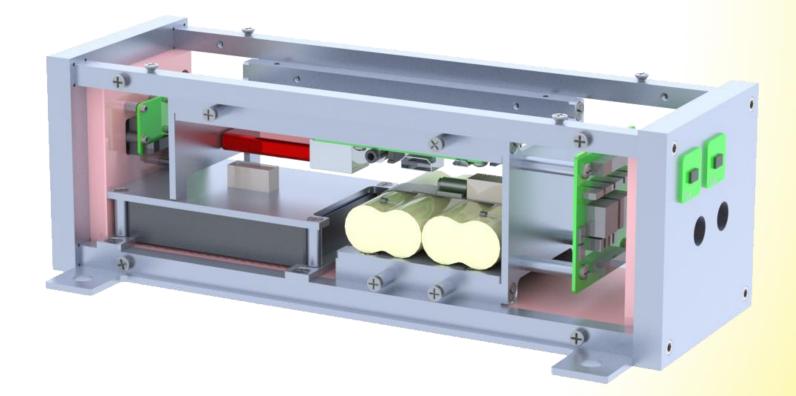


 Milestone Task Time Margin 	Jan. 30-Feb.	5 Feb. 6-12	Feb. 13-19	Feb. 20-26	Feb. 27-Mar.	5 Mar. 6-12	Mar. 13-19	Mar. 20-26	Mar. 27-Apr. 2	Apr. 3-9	Apr. 10-16	Apr. 17-23
Component Testing												
Subsystem Testing												
Test Status Review												
Integration Testing												
Testing End Deadline										•		
Symposium												

Project Design Critical Project Analysis Risks Verification Remainin g Work 78

Thank you!

We welcome your feedback!



Project Design Critical Project Analysis Risks Verification & Remainin & Rema



BACKUP



References



[1] Irom, Farokh, Duc N. Nguyen, and Gregory R. Allen. "Single Event Effect and Total Ionizing Dose Results of Highly Scaled Flash Memories." 2013 IEEE Radiation Effects Data Workshop (REDW) (2013): n. pag. Web.

[2] Powers, Charles E., and Stephen Waterbury. "Outgassing Data for Selecting Spacecraft Materials System." National Aeronautics and Space Administration. N.p., 13 Jan. 2016. Web. 15 Nov. 2016.

[3] Zwicker, Andrew P., Josh Bloom, Robert Albertson, and Sophia Gershman. "The Suitability of 3D Printed Plastic Parts for Laboratory Use." American Journal of Physics 83.3 (2015): 281-85. Web.

[4] Fluitt, Daniel. "Feasibility Study Into the Use of 3D Printed Materials in CubeSat Flight Missions." (2012): n. pag. Web. 14 Nov. 2016.



Image Credits



LASP Irradiance Data - http://spot.colorado.edu/~koppg/TSI/Publications/2007_Kopp_TRF_SPIE.pdf

HiWind Gondola Photos - http://stratocat.com.ar/globos/fotos/hiwind11b.jpg

HiWind CAD Models - Email from HAO-NCAR

Raspberry Pi - http://uk.rs-online.com/web/p/processor-microcontroller-development-kits/8968660/

SEU Chart – "Single Event Effect and Total Ionizing Dose Results of Highly Scaled Flash Memories."[1]

SLC - http://mx-technology.com/h5/en/flash2.php?sid=38

MLC - https://www.amazon.com/dp/B013CCTNKU/ref=twister_B0148N1COC?_encoding=UTF8&psc=1

Environmental Chamber – User's Manual G-Series Elite Family

EDAC - http://www.markertek.com/product/edac-106/edac-elco-516-020-000-402-20-pin-male-plug-withfixed-nut

Battery - http://www.all-battery.com/li-ion1865072v3350mahbatterypcbmodulewith24awgbareleads-34042.aspx

Avantes Spectrometer - http://www.avantes.com/products/spectrometers/compactline/item/723-avaspec-mini

Calibration Equipment – Alcor User's Manual

Humidity Sensor – http://www.digikey.com/product-detail/en/te-connectivity-measurementspecialties/HPP804B130/HPP804B130-ND/697732

Temperature Sensor – <u>https://www.sparkfun.com/products/11931</u>

Pi Header - http://www.raspberrypi-spy.co.uk/2014/07/raspberry-pi-b-gpio-header-details-and-pinout/



Image Credits



Resistor - http://www.digikey.com/product-detail/en/riedon/PF1262-15RF1/696-1682-5-ND/2447965

Foam - <u>https://www.grainger.com/product/GRAINGER-APPROVED-Foam-</u> Sheet-5GCT5?functionCode=P2IDP2PCP



Table of Contents



Overview	Design Solution	CPEs	Analysis	Risks	V & V	Remaining Work
Outline Project Motivation/Description <u>HiWind Gondola & Flight</u> <u>CONOPS</u> <u>Functional Requirements</u> <u>PDR Changes</u>	Overall System Assembly System Overview Exterior Spec Pi Data Sensors Power Thermal Camera ADS	<u>CPEs</u>	Structural <u>Motivation</u> <u>Design</u> <u>Manufacturing</u> Thermal <u>Motivation</u> <u>Temps</u> <u>Control</u> <u>Assumptions</u> <u>Boundary</u> <u>Analysis</u> Power <u>Motivation</u> Design	<u>Matrix</u> <u>High</u> <u>Moderate</u>	Plan Func Requirements Spec Calibration TVAC Env Camber FlatSat Photodiode Testing Camera Testing	<u>Team Struc</u> <u>Work Breakdown</u> <u>Gantt</u> <u>Cost Plan</u> <u>Test Plan</u>
	<u>FBD</u>		Budget Losses Case I Case II Mock Data C&DH Motivation Overview SEU	Backups <u>FBD</u> <u>HiWind</u> <u>Sensitivity</u> <u>Thermal</u> <u>Thermal Sims.</u> <u>Power</u>	Outgassing Software Spectrometer Sensors Camera Port Mapping	Off-Sun Angle Testing <u>TVAC</u> <u>FlatSat</u> <u>Photodiode</u> <u>Camera</u>
			ADS Motivation Angle Determination Camera Motivation FOV/Filter	Data Storage Component List Manufacturing Tolerances Renders		<u>Tech Drawings</u>

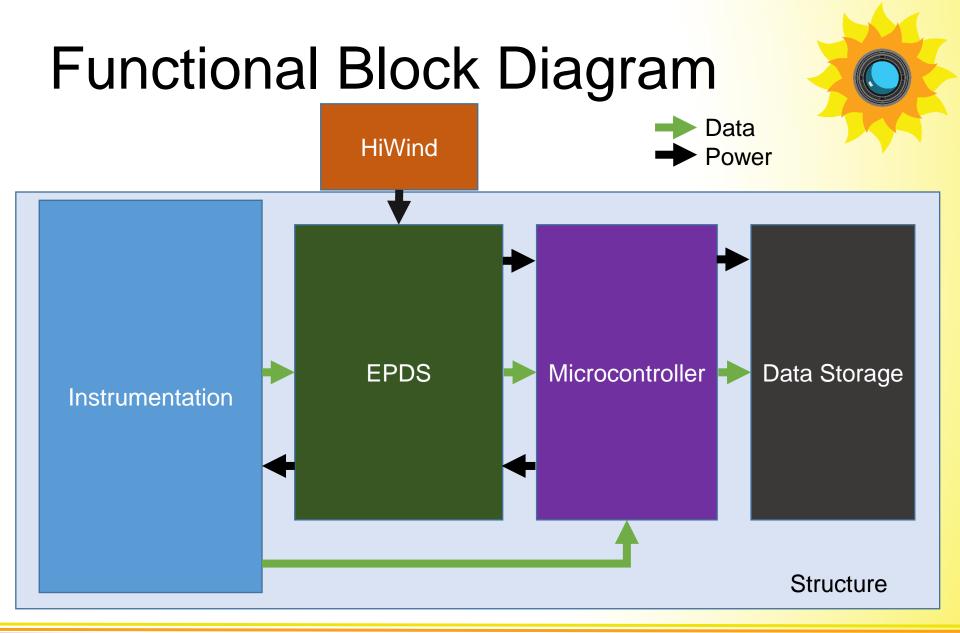


FlatSat Testing Plan



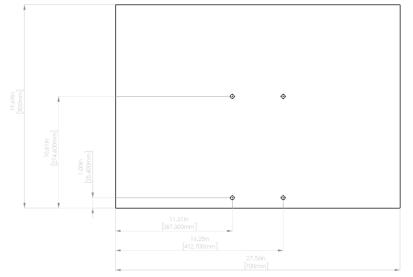
Shift	Person	Shift	Person
Fri 16:00-20:00	Katie	Sat 16:00-20:00	Jenny
Fri 20:00-00:00	Lance	Sat 20:00-00:00	Jeremy
Sat 00:00-04:00	Brandon	Sun 00:00-04:00	Katie
Sat 04:00-08:00	Alec	Sun 04:00-08:00	Russell
Sat 08:00-12:00	James	Sun 08:00-12:00	Jenny
Sat 12:00-16:00	Russell	Sun 12:00-16:00	Lance







Interface with HiWind



- Structure to be mounted with four 3/8 inch bolts
- Mounted normal to HiWind's solar panels

Risk	Cause	Mitigation
Critical Mechanical Interface Failure	Catastrophic failure of the mounting system	Use of locking bolts, and bolts rated at high loadings than expected.
Angle Error on Installation	RADIANCE installed at an off angle from HiWind's sun pointing face	Bolt pattern on RADIANCE and HiWind to minimize rotation and mounting errors.



HiWind Integration: Elec.

- > Power received from HiWind
 - > 15W at 28V
- > EDAC 20 pin connector
 - Subject to change

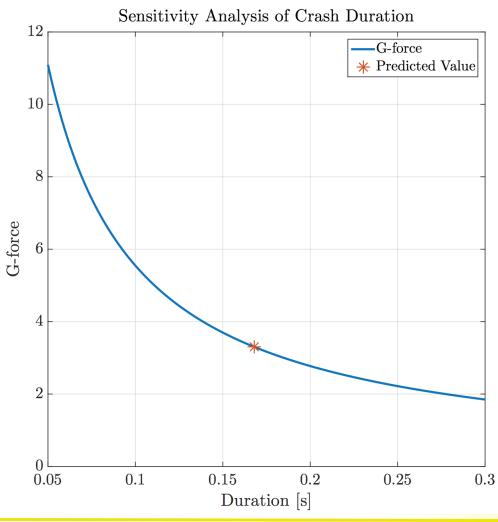


Final connector type has yet to be determined from HiWind

Risk	Cause	Mitigation		
Supply power failure	Power supply to RADIANCE is ended prematurely	RADIANCE draws off of battery as long as possible		
Supply power interruption	Power to the RADIANCE system is temporarily interrupted	RADIANCE automatic restart when power resumes		
Any voltage received or produced by the RADIANCE system that is outside the expected voltage input range	Errors in circuit design or unintentional changes to circuit configuration in flight.	Design proper circuit interface protection that prevents back current and power surges		
Reverse current through electrical interface	Lack of protection circuitry on RADIANCE	Design of reverse current protection circuit		
Critical RADIANCE battery failure	RADIANCE's Lithium ion battery, which can fail from improper charging or puncture	Proper circuit protection and structural design that minimizes sharp points of contact with the battery		



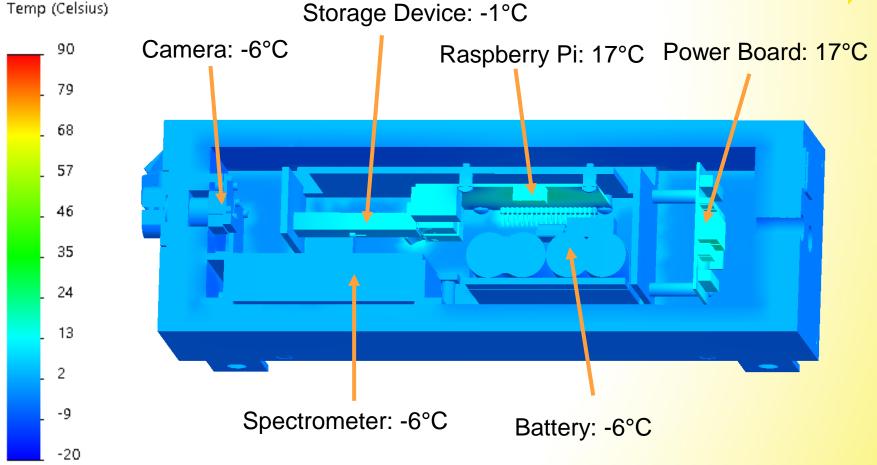
HiWind Landing Sensitivity





Thermal Analysis

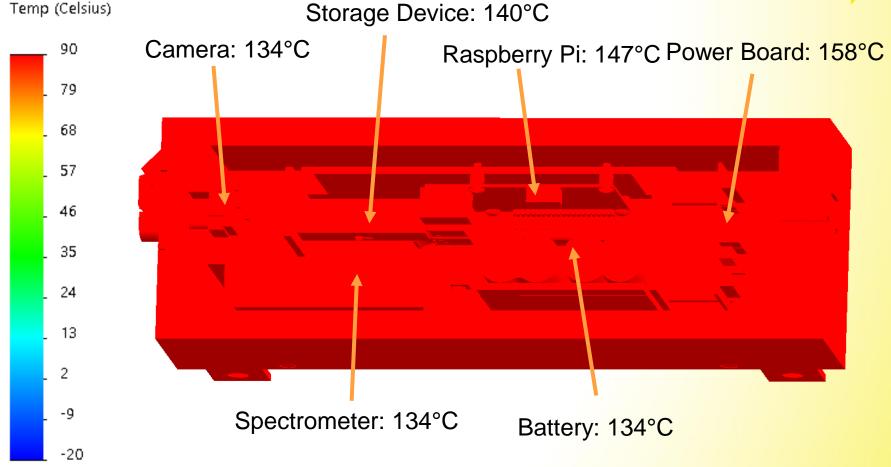
Passive control, on the ground, steady state model





No Radiative Coating

Passive control, during cruise, steady state model

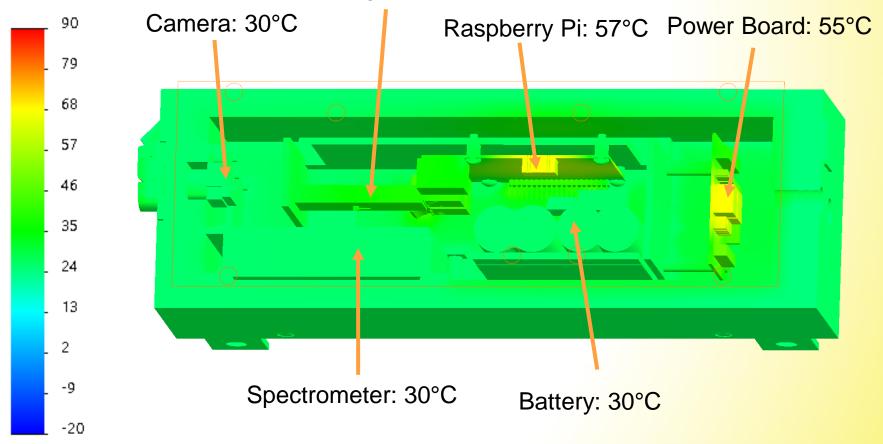




Emissivity = .5

Passive control, during cruise, steady state model



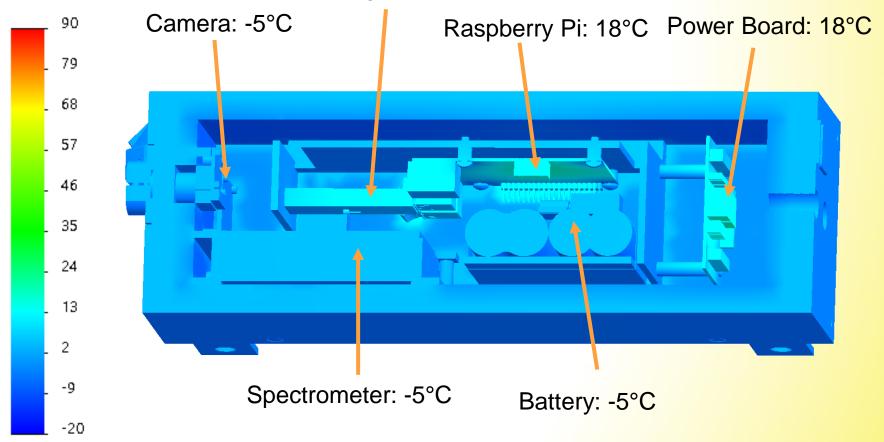




Emissivity = .5

Passive control, on the ground, steady state model









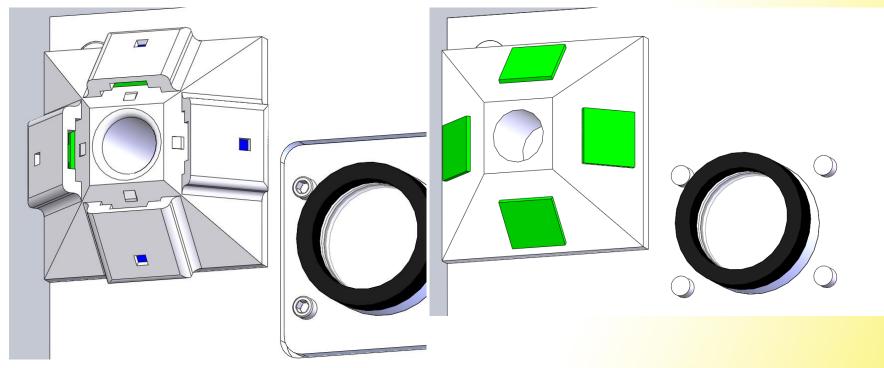
Thermal Simulations Setup



Step 1: Simplify Geometry

Before

After





Step 2: Apply Boundary Conditions

Temperatures Power Outputs

Radiation

7.

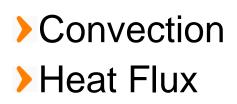
Parts

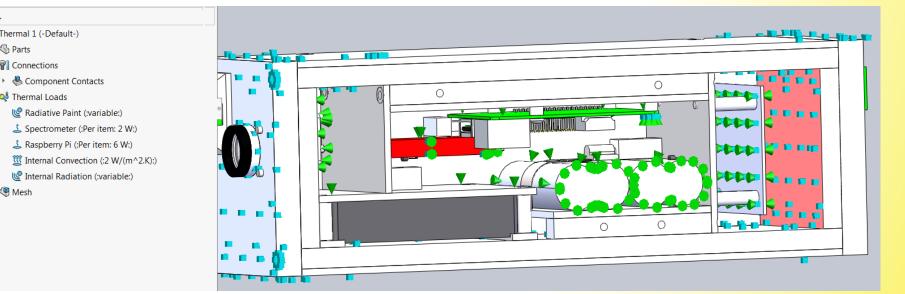
Thermal 1 (-Default-)

Connections

Thermal Loads

Mesh









Step 3: Apply Contact Conditions

- Bonded Contacts:
 - Perfect Thermal Conduction
- Insulated Contacts:
 - Resistance between components
- Compatible Mesh
 - Nodes and members line up between elements
- Incompatible Mesh
 - Mesh optimized per component ignoring surroundings



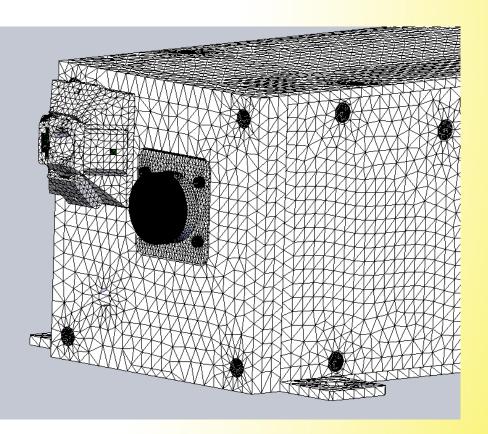


Step 4: Create Mesh

Remesh until it works

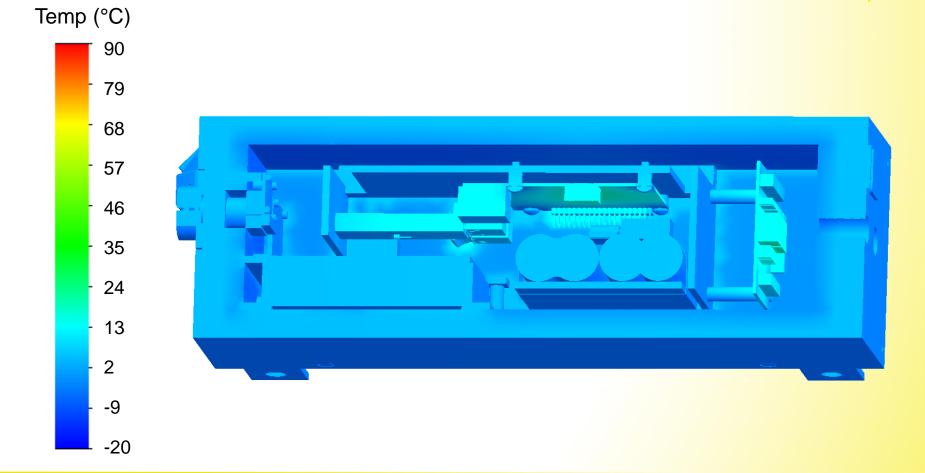
Jacobian equations derived from nodes

Min element size: .06 mm
Max element size: 17 mm





Step 5: Run Thermal Study Working results!



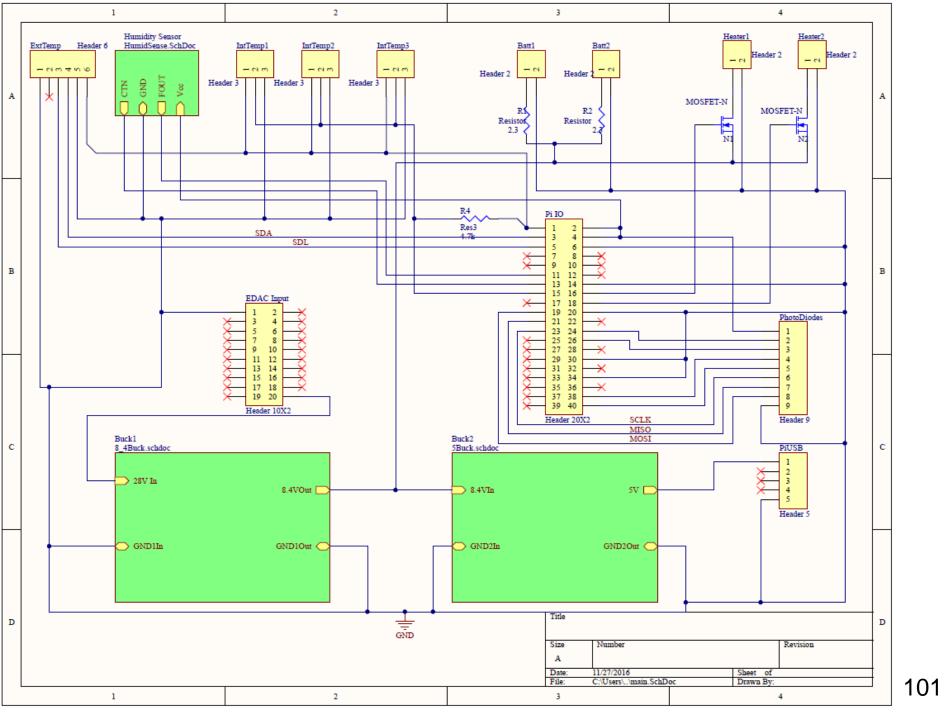


Future Thermal Plans

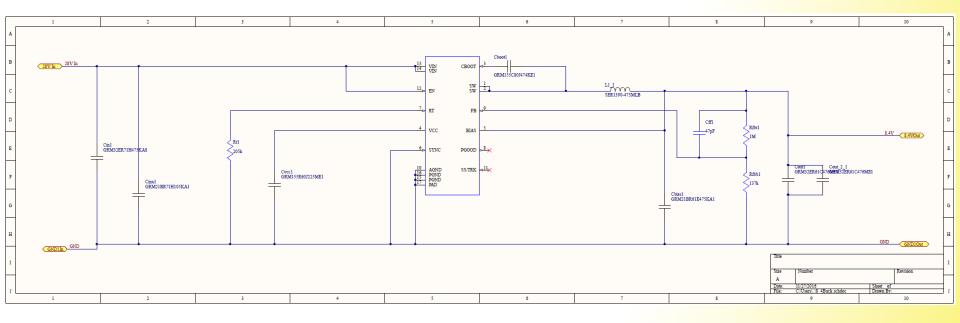


- Run full transient study of entire flight profile with maximum time step of 1 minute
- Run high fidelity modeling in Thermal Desktop
- Run individual components through transient to observe effects of convection and spot heating
- Provide sensitivity analysis for possible construction flaws



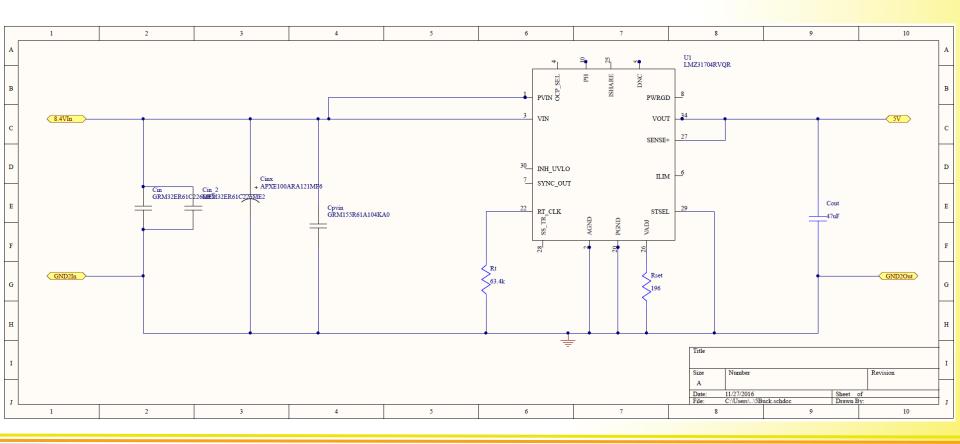






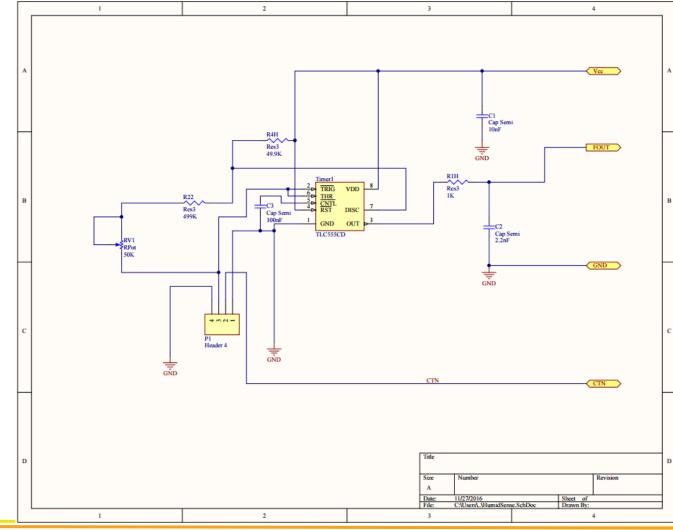


8.4 to 5V Buck Converter





Humidity Sensor





Raspberry Pi Power Draw

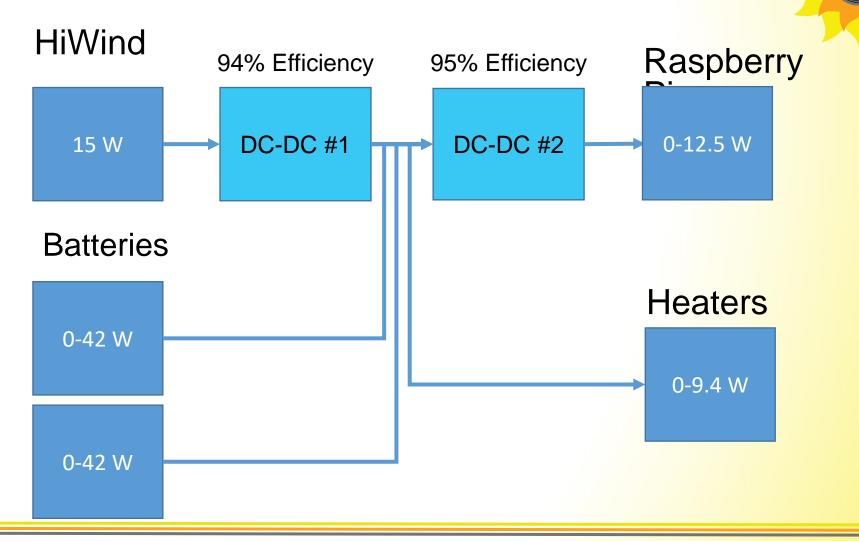
State	Average Power Draw	Max. Power Draw
Boot	1.75 W	3.75 W
Idle	1.5 W	N/A
Stress	4.25 W	6.7 W

 Only accounts for Pi, not power drawn from USB ports
 Assumed average stress power draw value for calculations needing Pi power draw

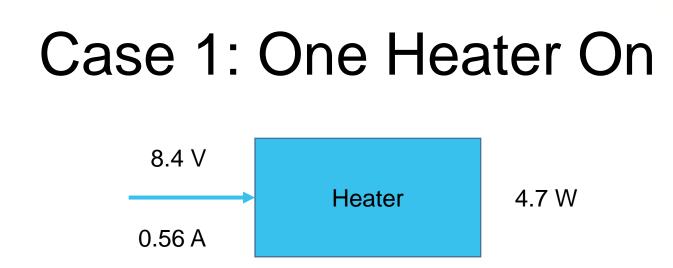




Power Sources





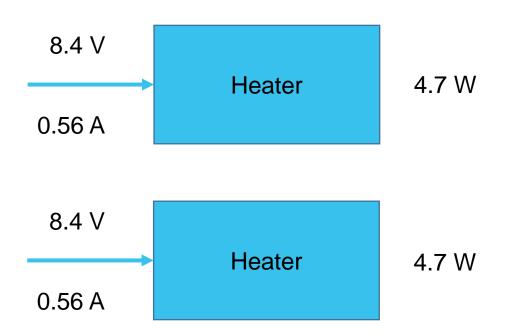


Allows for 8.8 W to the Pi
 Nominal Pi Power draw





Case 2: Two Heaters On



Heater Power Draw– 9.4 W Pi Power Draw – 8.1 W Total Overall Draw – 17.5 W = 14.1 From HiWind + 3.4W from Batteries



Battery

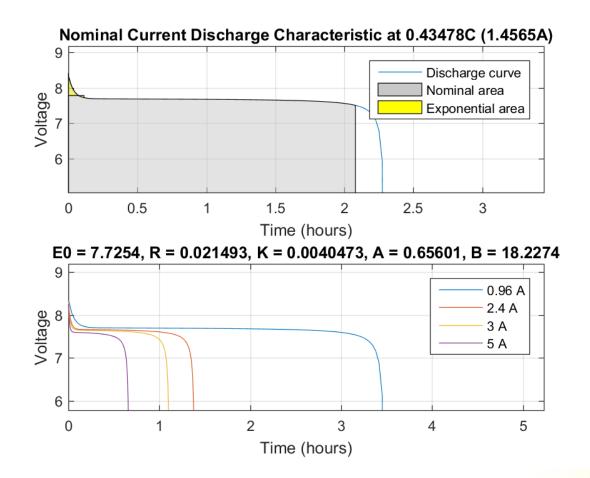


Li-Ion Battery
3.35 A-hr capacity
Built in charge protection
2 cell package
7.2 V nominal
5.0 A maximum draw

Thermal Characteristics
 Charging: 0° to 60° C
 Discharging: -20° to 60° C



Battery Draw



>0.96 A -> Nominal battery draw > 2.4 A -> Cruise power draw > 3 A -> Max system draw $>5 A \rightarrow Max$ battery draw



MOSFET Control

Use equation for average

$$\bar{y} = \frac{1}{T} \int_0^T f(t) dt = \frac{1}{T} \left(\int_0^{DT} y_{\max} - \int_{DT}^T y_{\min} dt \right)$$

Assume minimum voltage is zero:

$$y_{\min} = 0$$

Carry out integral for square wave:

$$\bar{y} = Dy_{\max} \implies$$

Heater voltage is linear function of duty cycle!



MOSFET Selection





Part Name	P-Channel MOSFET 20V 24A - low Vgs(th)
V_gs	0.7V
Max Power Dissipation	60W
I_DS @ 3.3V	30A
Typical Rise Time	On: 30 nS Off: 200 nS



Data Storage - SLC



Measurement	Size/data point	Frequency	Total
Spectrometer	16.384 kB	1 Hz	10.55 GB
External temperature	4 B	1 Hz	5.273 MB
Internal temps (x6)	24 B	1 Hz	31.638 MB
Humidity	4 B	1 Hz	5.273 MB
Photodiode (x4)	32 B	1 Hz	42.1875 MB
Sun angle	4 B	1 Hz	5.273 MB

C++ binary data files: floats are 4 bytes, doubles are 8 bytes



Data Storage - MLC



Measurement	Size/data point	Frequency	Total
Camera images	1.8 MB (max)	1/60 Hz	40.5 GB

All test images were within a few bytes of 0.9 MB. We doubled it to be sure.



SLC Micro SD Card



Panasonic Electronic Components RP-SMSC02DA1		
Storage 2GB		
Price	ce \$35.85 without margin	
Temperature Range -40 °C to 85 °C		



- Reasons for selection:
 - Easy install of OS
 - Resistant to single event upsets



Component List

Components	Quantity
Manufactured Parts	26
3D Printed Parts	2
Electrical Boards	6
COTS	20
Screws	75
Spacers	26
TOTAL	155

Does not include wires, cables, and other miscellaneous interfaces.



Manufacturing Tolerances



Parts to be 3D printed:

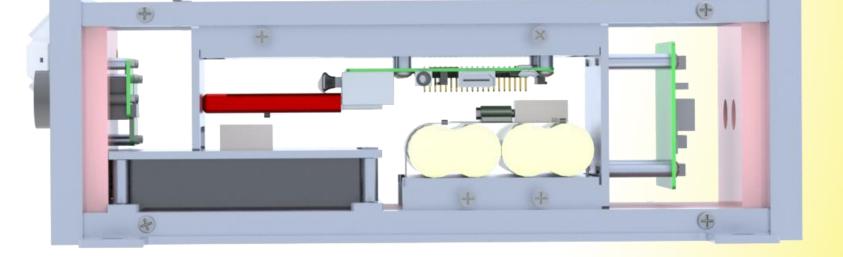
- Photodiode array
- Neutral density filter threads
- >3D Printer: ±10 µm layer thickness ±140 µm in the x/y directions

>CNC Mill: ±0.002"





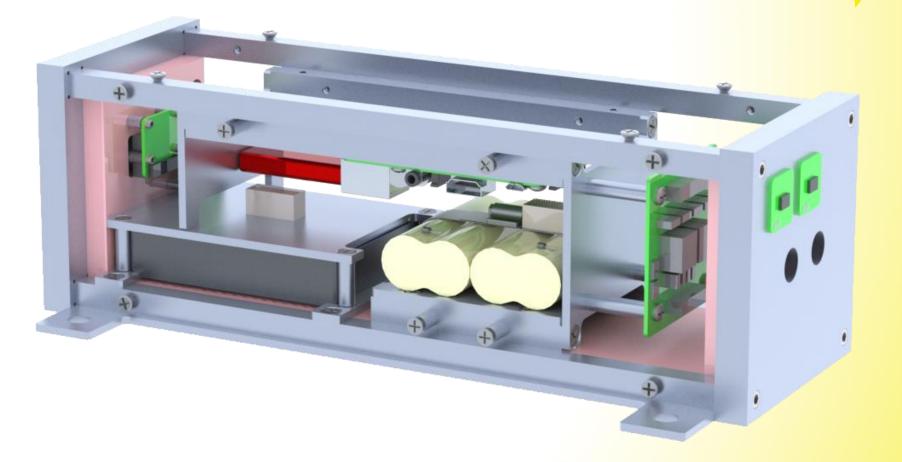
Renders







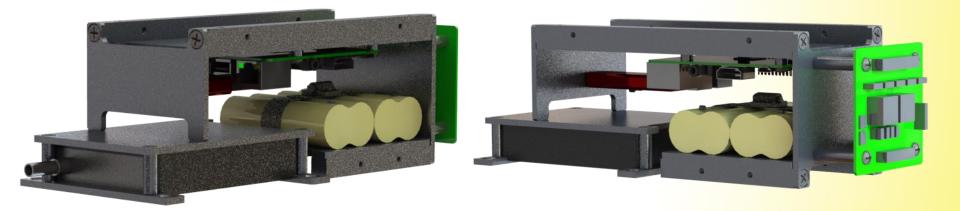
















Outgassing of 3D Printed Materials



*Low Outgassing" is defined by NASA using TML and CVSM

TML = Total Mass Lost

—TML < 1.0%

CVCM = Collected Volatile Condensable Material

—CVCM < 0.10%

Bobby's Lab has a FormLabs Form 2 Printer

Uses methacrylate photopolymer resin, which is a proprietary material

Similar photopolymer resins have good outgassing profiles



Outgassing of 3D Printed Materials

Material	TML	CVCM	Reference
ABS Plastic, 3D Printed	0.94%	0.04%	NASA
PET Plastic (Makergeeks.com)	0.61%	0.05%	NASA
PLA Plastic (Makerbot)	0.56%	0.01%	NASA
P430 ABS Plus	0.37%	0.00%	NASA
ABS Plus	0.63%	0.08%	NASA
Acrylic Safety Glazing, Polymetholmethacrylate	0.68%	0.00%	NASA
PLA Plastic (Replicator 2 from Makerbot)			PPPL
Objet FullCure720 Photopolymer Resin	0.74%		CalPoly
DSM Somos Prototherm 12120 Photopolymer Resin	0.92%	0.10%	CalPoly
Windform XT Carbon Fiber Filled Nylon	0.14%		CalPoly



Outgassing Conclusions



All 3D printable materials that NASA researched are considered "low outgassing"^[1]

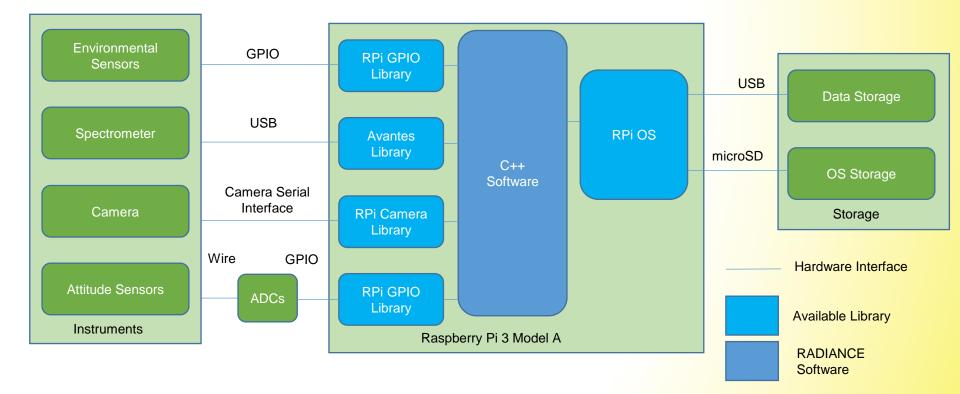
Princeton Plasma Physics Laboratory (PPPL) found that PLA Plastic is suitable from 0.00013 Pa to 101325 Pa (not an ultra-high vacuum)^[2]

Cal Poly found three photopolymer resins that are suitable for low outgassing^[3]



Software Interfaces



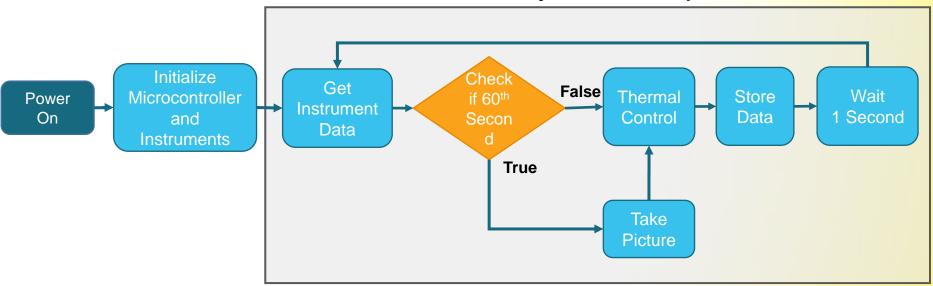




Software Flow



System Loop



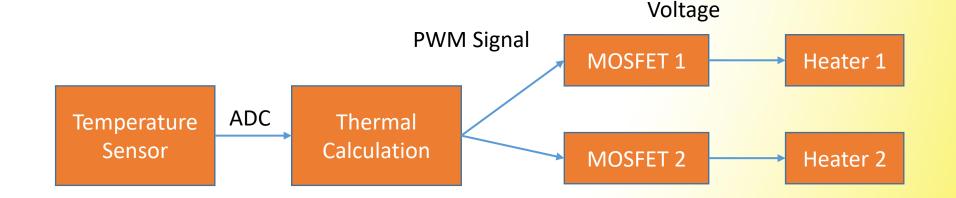


Heating Algorithm

Pseudocode:

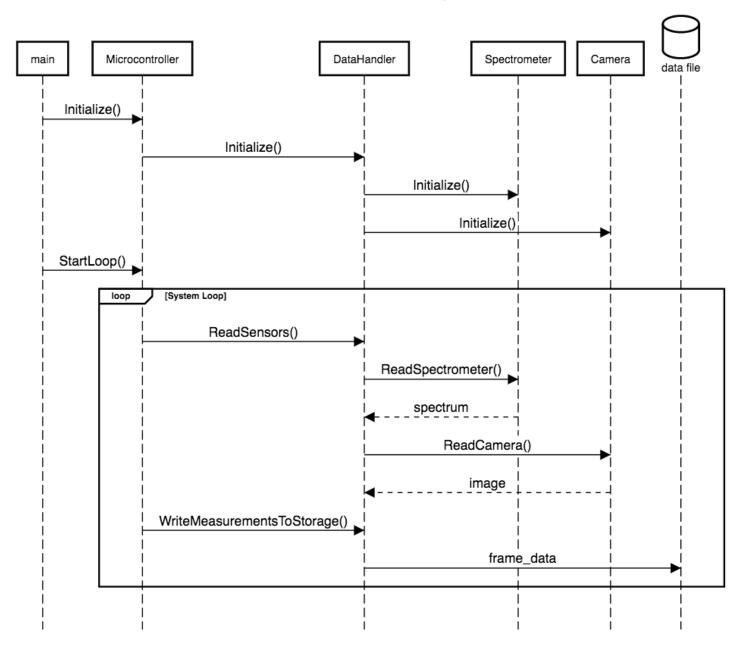
If(Temp < MinTemp) TurnHeatersOn = 1; elseif(Temp > MaxTemp) TurnHeatersOn = 0; end

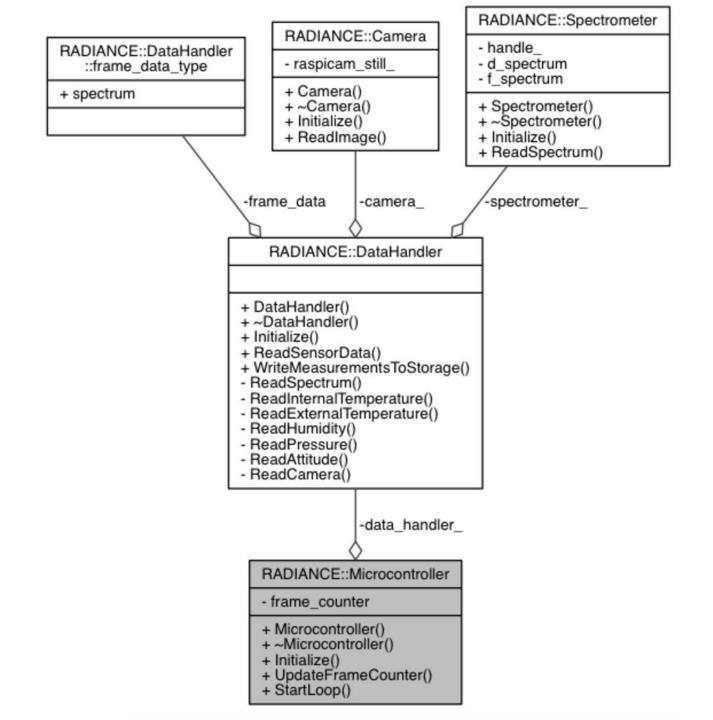
- One calculation for each heater
- Approximate execution time: <1ms





RADIANCE Software Sequence





Spectrometer



Requirement	Implementation	
Measure spectra from 250nm to 1000nm	Avantes Mini 2048L-UVI25 measures 200nm-1100nm	
Measure with resolution of 1nm	Resolution of 1.4nm	Approved by customer
Must be calibrated	Use provided Avantes software in conjunction with Dr. Marshall's light calibration source	





- > Reasons for selection:
 - > Fit spectra requirements
 - C++ Library for use on Rasbian
 - Cheapest one we could find



Spectrometer Calibration



Specification	Approach	Resource	External Source
Calibrate spectrometer	Characterize spectrometer output against known light source	 Light source with known output Dark room Optical cloth 	Dr. Bob Marshall Dr. Scott Sewell, HAO
Measure from 250 to 1000 nm	380 nm to 1068 nm with errors below 3% from 460 nm 936 nm	Light source with known output	Dr. Bob Marshall
Measure from 250 to 1000 nm	Test full-range readings	Sunny day	N/A



Spectrometer: Calibration



Use Avasoft calibration software

Specify parameters of calibration equipment and size of sampleport (fiber cable)

	Intensity Calibration: 5827347UA	
Settings for spectrometer 5827347UA - (5827347UA) Measurement Settings Digital IO Wavelength Coefficients Light Sources Control Irradiance Custom Reflectance Color Temperature [K] 2850	Status Integration Time [msec]: 20,00 * *	1.300 1.250 1.150 1.150 1.150 900 900 900 900 900 900 900 9
		Close



External Sensors



Requirement

Implementation

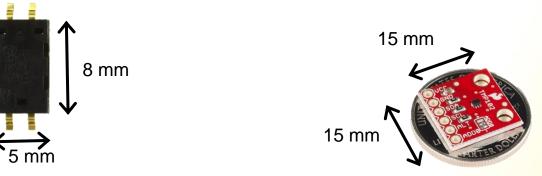
Take environmental measurements

TMP102 Temperature Sensor HPP04B130 Humidity Sensor

- > Reasons for selection:
 - Humidity
 - Only one that can survive external environment

> Temperature

- > Can survive environment
- Provides accurate measurements at low temperatures (± .7C at -55C)





A Modest Proposal: Pressure



1. Temperature

Almost all manufacturers only test pressure sensors from -40C to 85C or 125C for industrial applications. While they can survive lower than that, the only way we can prove that to the PAB is to use a pressure sensor in excess of \$2000. We can run a tube from the interior to the exterior but that would provide inaccurate measurements.

2. Pressure

We are in an extremely low pressure environment. Even pressure sensors rated to "ultra-low" pressure environments can only measure 10 in H20. 200Pa (our environment) is equivalent to 0.8 in H20. To measure at altitude, we would not be able to measure on accent without a second sensor (once again that cannot be guaranteed to the PAB to survive temperature and would not operate on coldest part of accent.)

3. Time

This is not a requirement and the environmental data we measure is completely our decision. The pressure at cruise will remain almost constant, meaning the entire effort would be placed into only a few hours of time on accent out of 2 weeks of total time. In order to get a pressure sensor that we can guarantee to survive the environment and we can afford, we would need to submit it to tests at temperatures at least as low as -55C taking even more time.

4. Money

In order to achieve this, we would need to spend 3-4 times the amount it costs to do all of our other sensors. Without EEF funding this is now out of budget.



Requirement	Implementation	
Take images of visible spectrum	Raspberry Pi Camera Module v2.0	
Field of View of 5° (±1°)	FOV 6.32°	Approved by customer

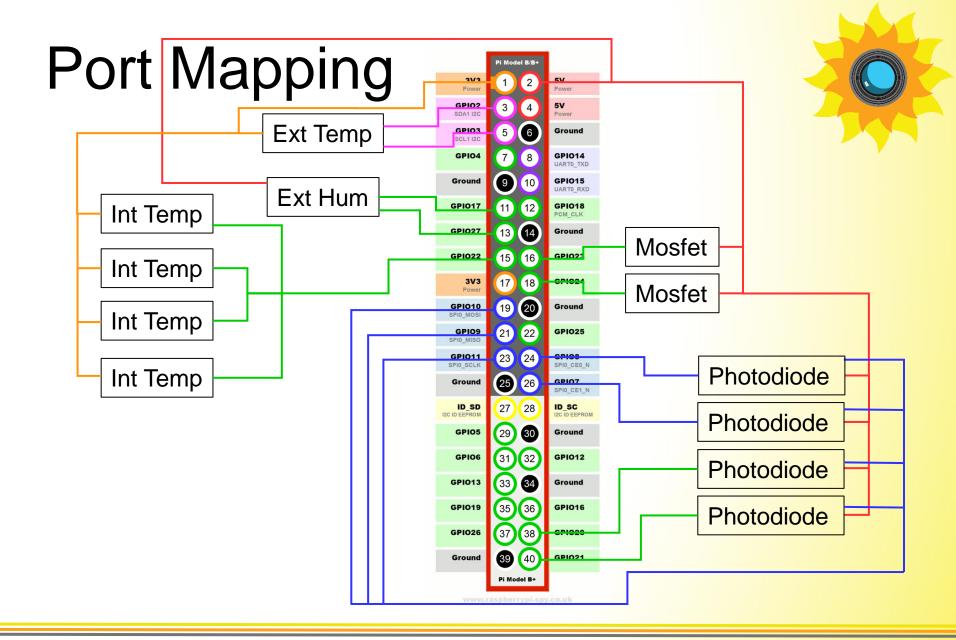


Camera

Example image at 18ft. Black circle is 2in in diameter. Approximately size of sun in the sky.

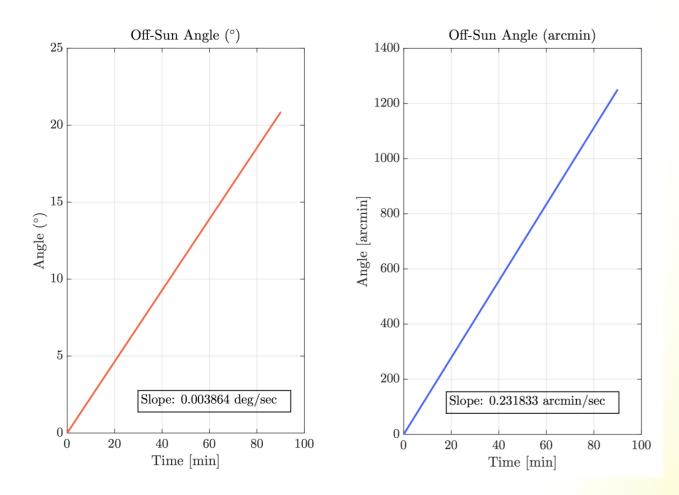


- > Reasons for selection:
 - Made for easy interface with Pi
 - Small form factor
 - COTS lens
 - > Adjustable





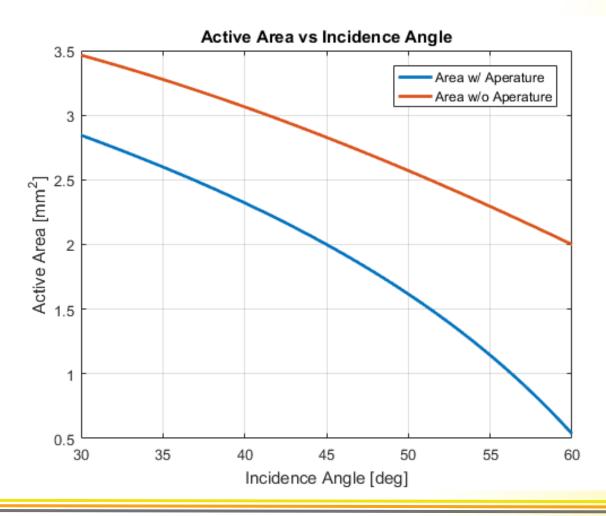
Off-Sun Angle Rates







ADS Aperture Sensitivity







ADS Noise Effects



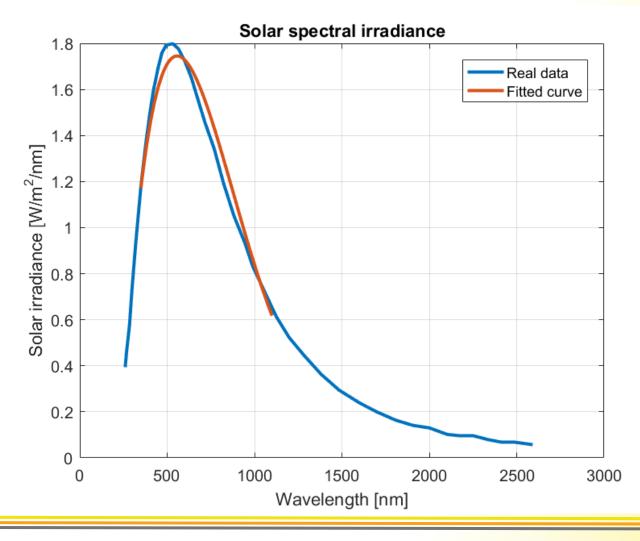
$$I_{shot} = \sqrt{2qBI_{sig}} \qquad SNR = \frac{I_{sig}}{I_{shot}}$$

> System bandwidth *B* is 1 Hz
> *q* is the charge of an electron (C)
> Dark current (2 nA) SNR = 49 dB
> Short circuit current (90 µA) SNR = 72 dB





ADS Spectral Response

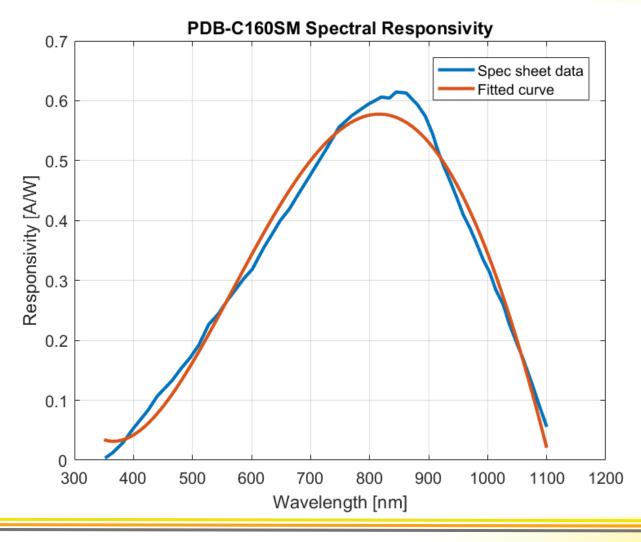








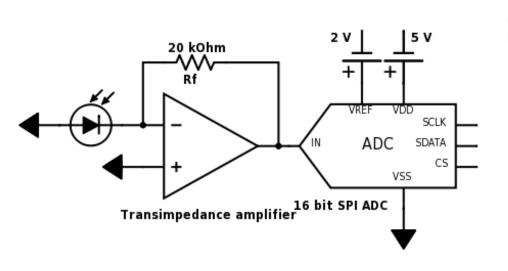
ADS Spectral Response







ADS Circuit Design



16 bit SPI ADC (x4)

- Require < 0.46 mV/DN</p>
- Achieves 0.03 mV/DN
- Max accuracy: ± 0.07' (assuming no noise)
- Actual (with shot noise): ± 0.1'

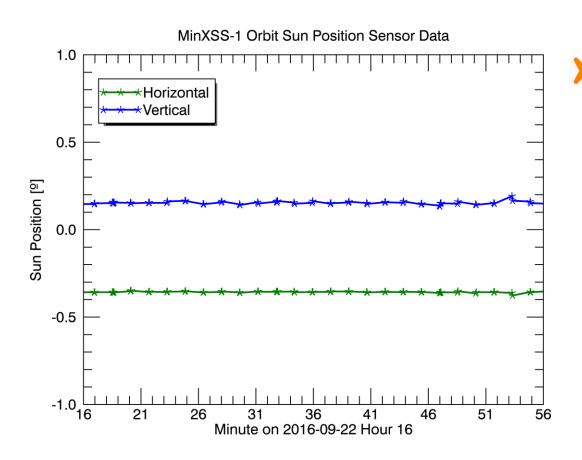
Purchasing a transimpedance amplifier (x4)

- Noise is specified by manufacturer
- Sophisticated design for noise reduction

Photodiode current between 30 µA and 340 µA



MinXSS Accuracy



 Standard deviation: 0.6 arcmin in either direction
 0.84 arcmin total error



Data Storage - SLC



Measurement	Size/data point	Frequency	Total
Spectrometer	16.384 kB	1 Hz	10.55 GB
External temperature	4 B	1 Hz	5.273 MB
Internal temps (x6)	24 B	1 Hz	31.638 MB
Humidity	4 B	1 Hz	5.273 MB
Photodiode (x4)	32 B	1 Hz	42.1875 MB
Sun angle	4 B	1 Hz	5.273 MB

C++ binary data files: floats are 4 bytes, doubles are 8 bytes





Data Storage - MLC



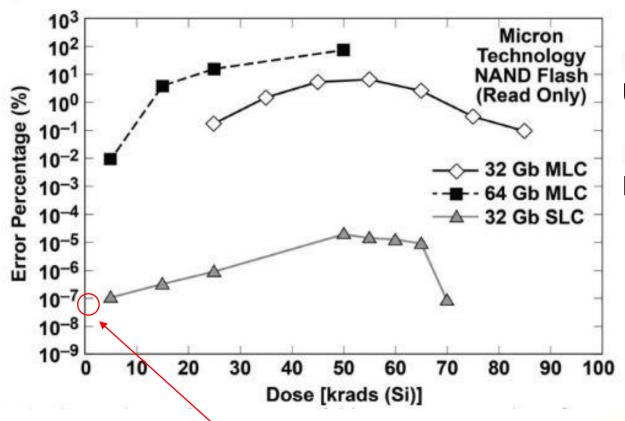
Measurement	Size/data point	Frequency	Total
Camera images	1.8 MB (max)	1/60 Hz	40.5 GB

All test images were within a few bytes of 0.9 MB. We doubled it to be sure.





Data Storage — SEU Risk



SEU = Single Event Upset
E.g. Bit flip
Total Ionizing Dose
Failure Experiment
Drives each exposed to radiation for total of 10 seconds
For reference: Satellites in LEO experience ~1 krad/year

Expect ~ .0384 krad over flight



TVAC & Environmental Chamber



Specification	Approach	Resource	External Source
Survive exterior environment at - 65°C	Environmental chamber testing	Environmenta I chamber	Dr. James Nabity
Operate at 5°C	Mimic cruise conditions	TVAC	Dr. Scott Sewell, HAO
Operate at 200 Pa	Mimic cruise conditions	TVAC	Dr. Scott Sewell, HAO
Verify thermal model	Additional temperature sensors on critical components and indicative points	N/A	N/A



FlatSat Integration Testing



Specification	Approach	Resource	External Source
Spectrum: 1/min	Software, data inspection	N/A	N/A
ENV data: 1/min	Software, data inspection	N/A	N/A
Camera images: 1/min	Software, data inspection	N/A	N/A
Spectrum and ENV data measurements recorded within 2 sec	Inspect data timestamps after test	N/A	N/A
All data stores in useable format	Insect data and run minimal plotting analysis after test to verify	N/A	N/A
System operates through 2 week cruise	Continuous test for 48 hours	24-hr Facility Power supply	Trudy Schwartz's Lab



Photodiode Testing



Specification	Approach	Resource	External Source
One arcminute precision	Mount to star tracker with better than arcminute precision	Star-tracking telescope from Sommers-Bausch Observatory (SBO)	Fabio Mezzalira, SBO
Analogous light source	Sun on a clear day	—	—
'Zero' condition	Star tracker pointing data	Star-tracking telescope from SBO	Fabio Mezzalira, SBO
	Confirm by post- processing camera images	Software, camera images	RADIANCE



Camera Testing

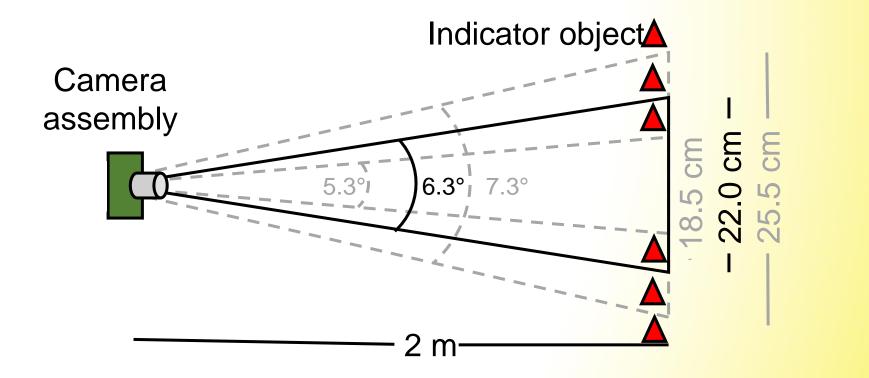


Specification	Approach	Resource	External Source
Images in focus	Visual inspection of test images	N/A	N/A
Analogous light source	Sun on clear day	Star Tracking Telescope	Fabio Mezzalira, SBO
4-6° FOV	Indicators at FOV boundaries	Non-specialized empty space, 2 m x 30 cm	ITLL
		Non-specialized indicator objects— textbooks, water bottles, cans, etc.	N/A



Camera Testing

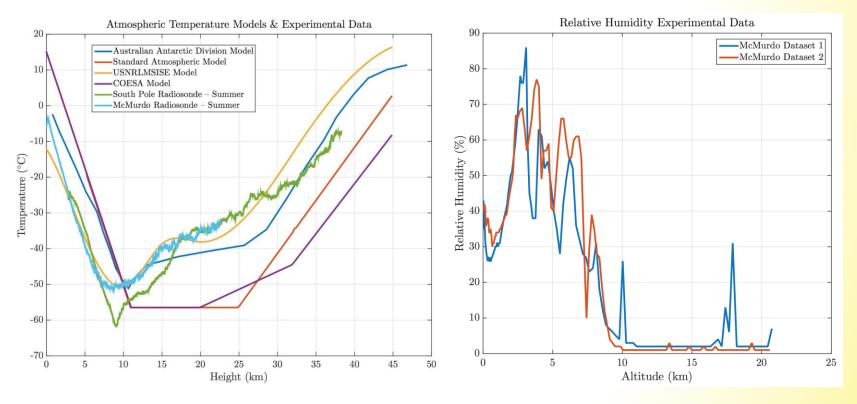
Validate field of view model





Atmospheric Models

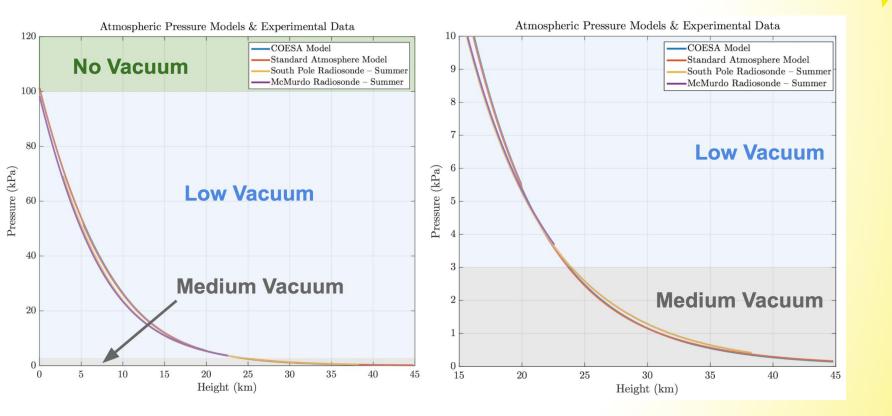






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Atmospheric Models

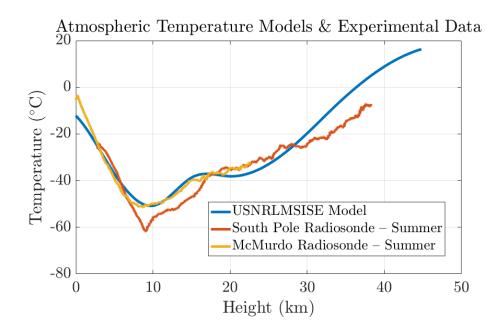




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Atmosphere Justification

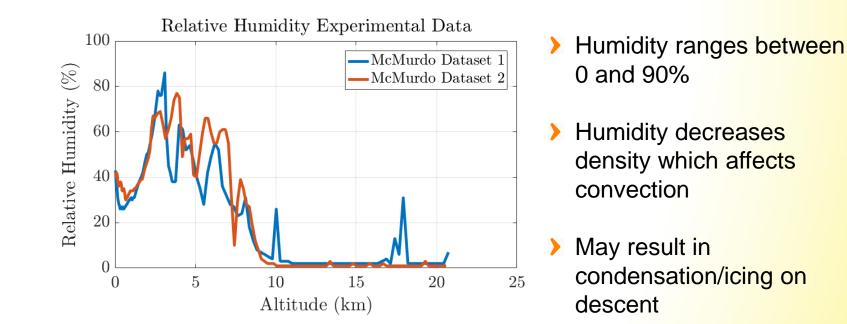


- Used USNRLMSISE model for continuity
- Both McMurdo datasets follow general trend of model

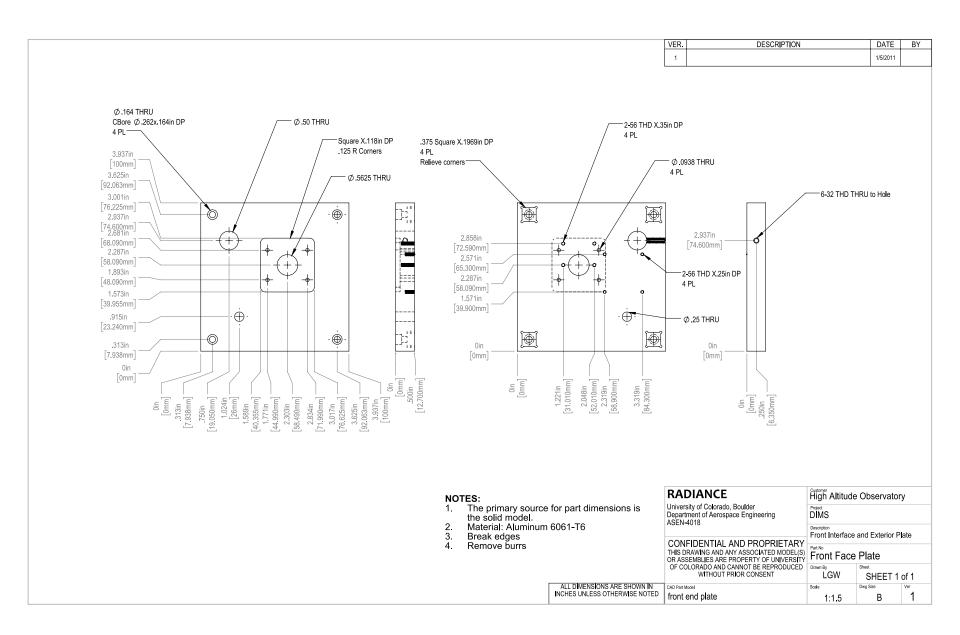


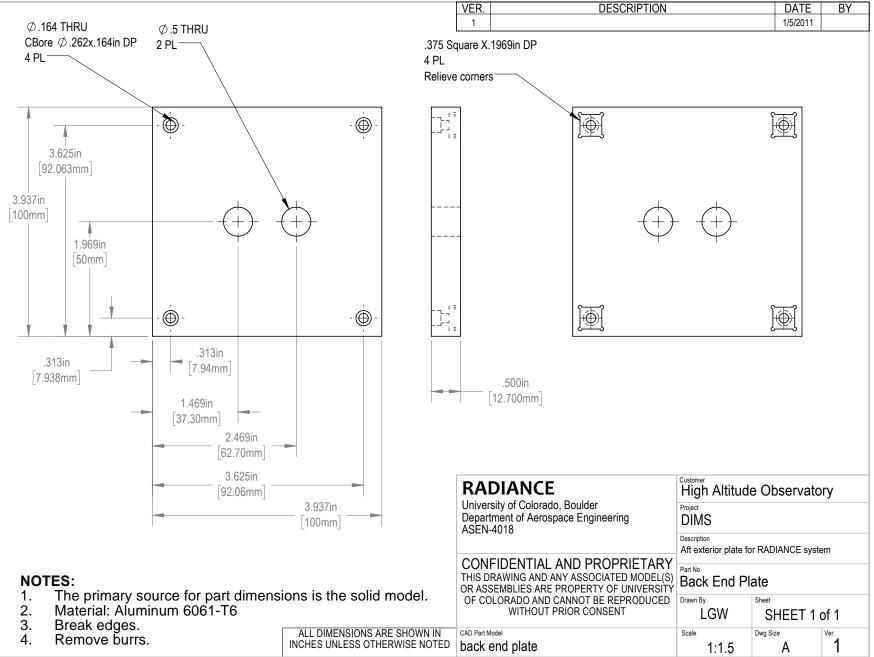
Atmospheric Humidity

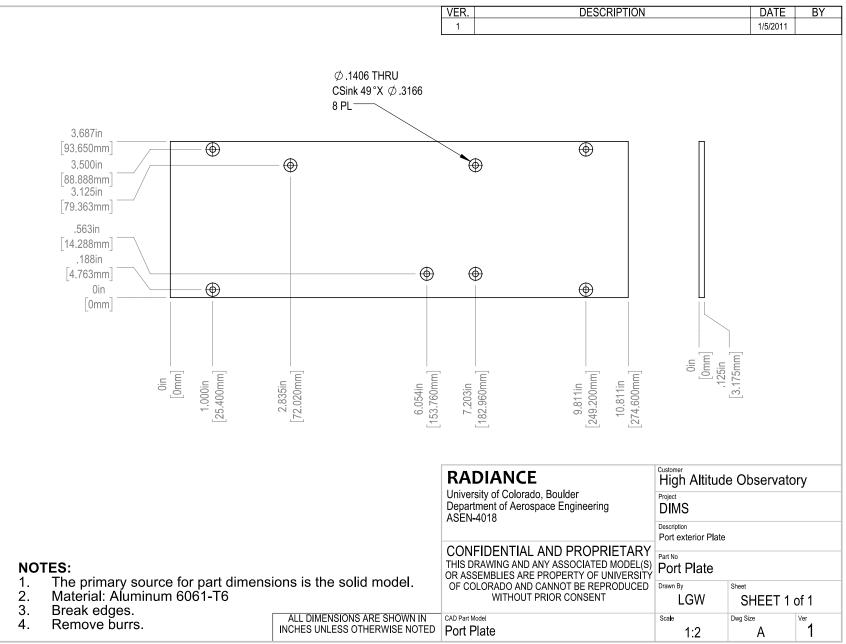


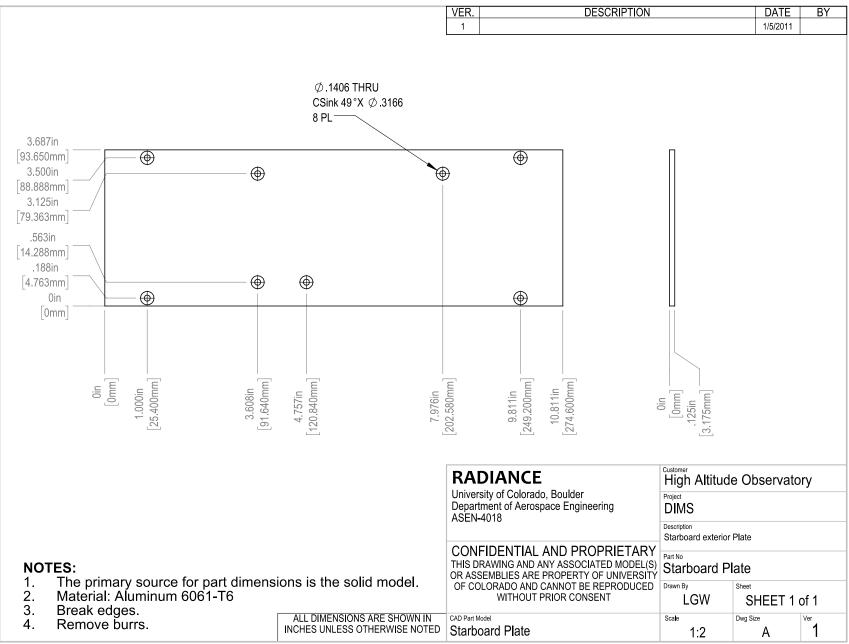


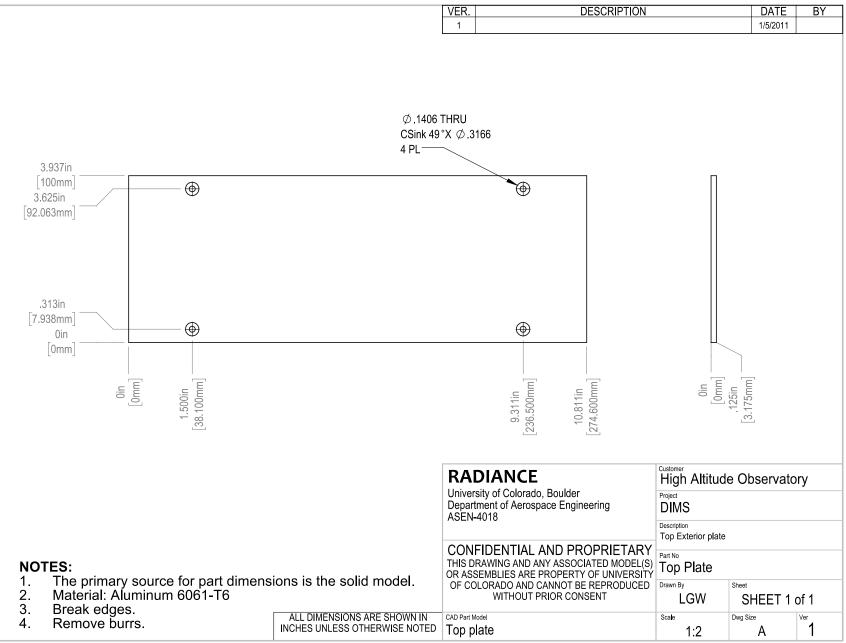


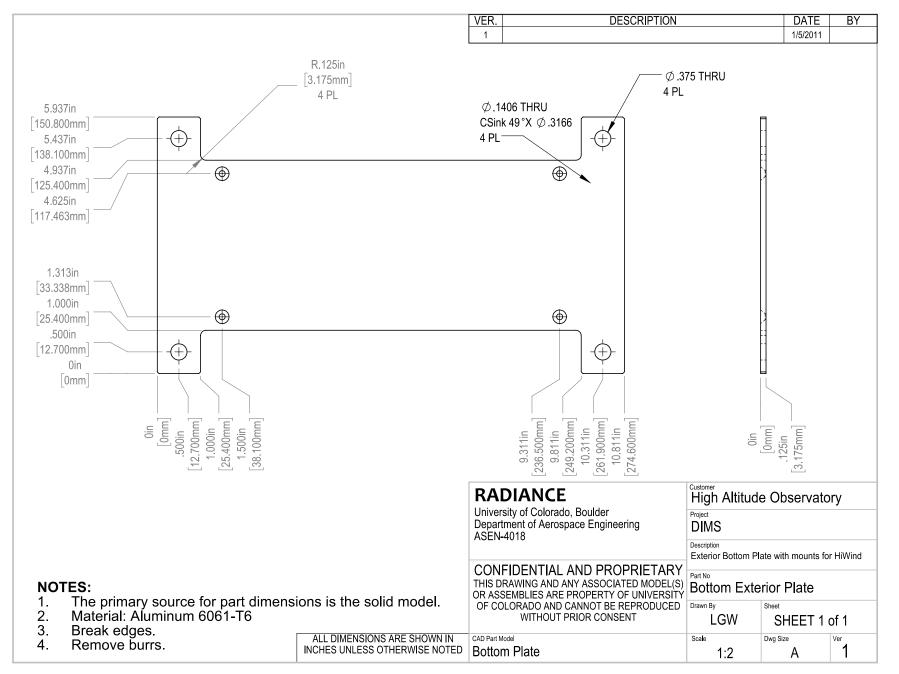


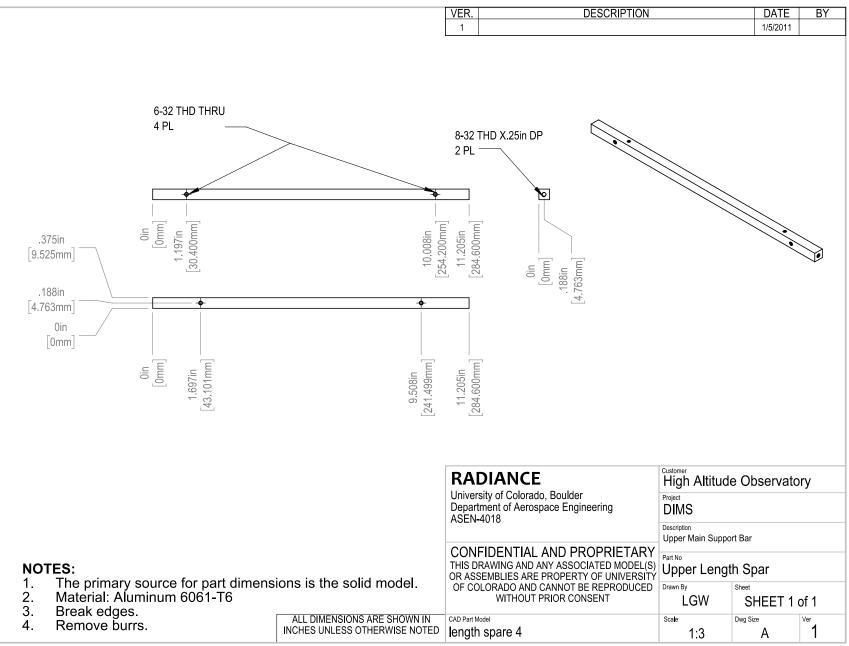


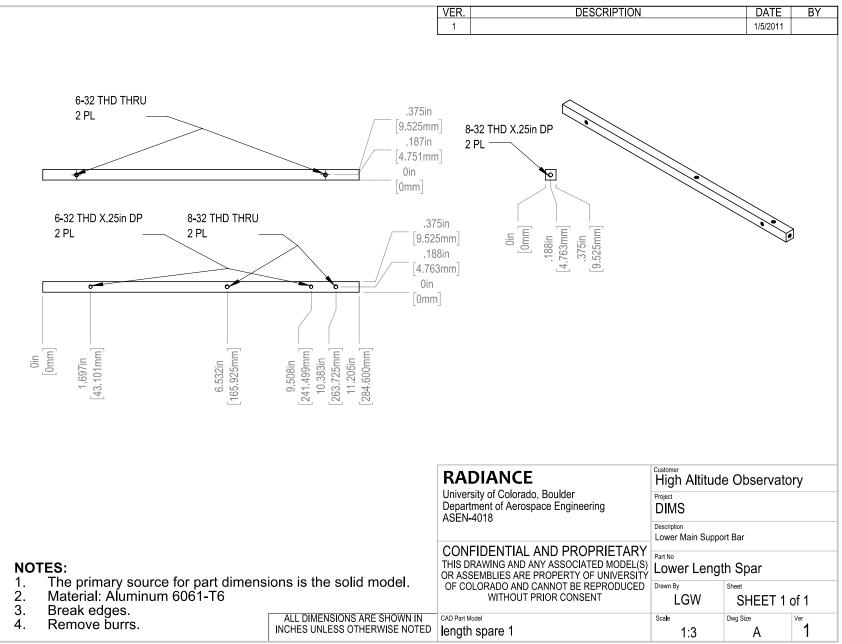


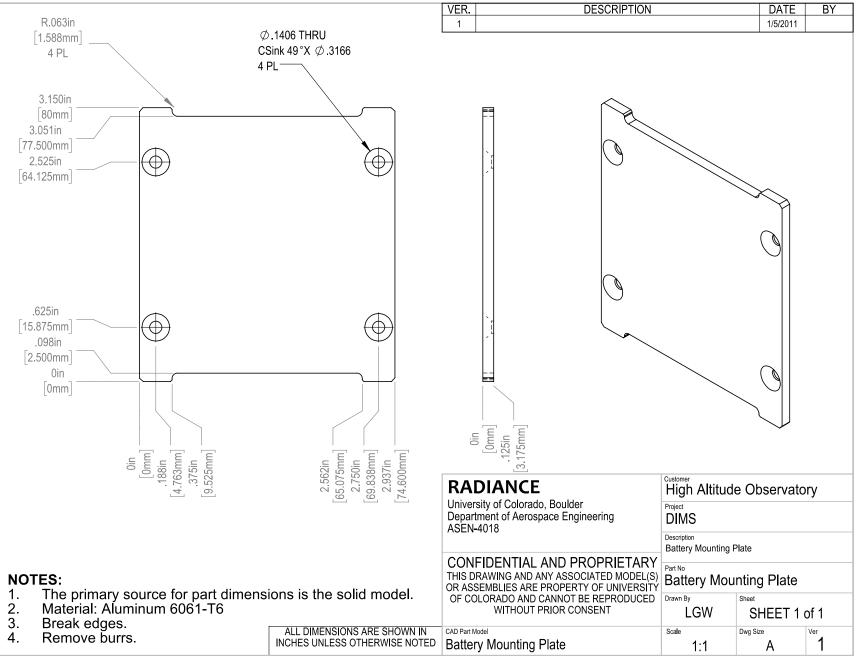


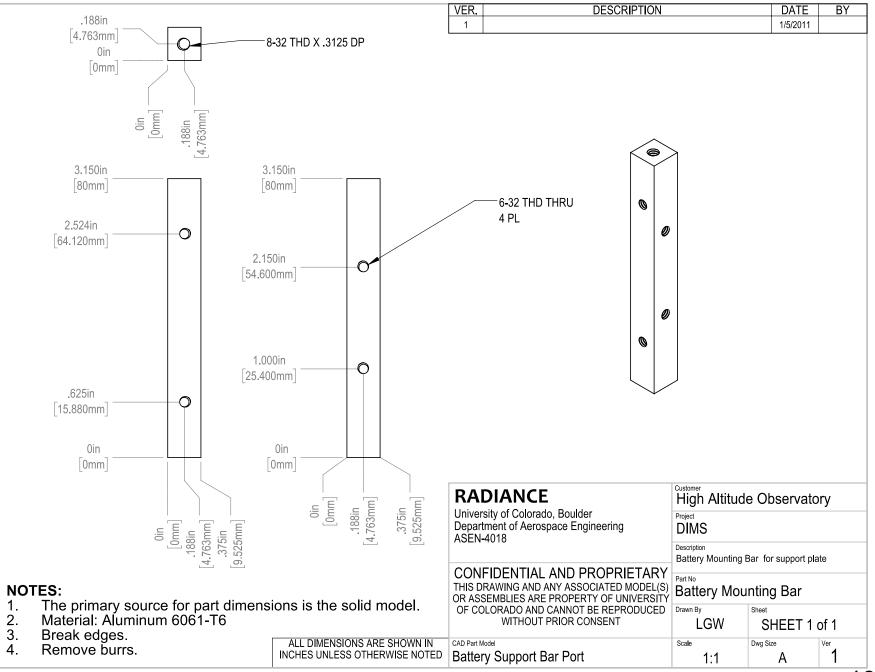


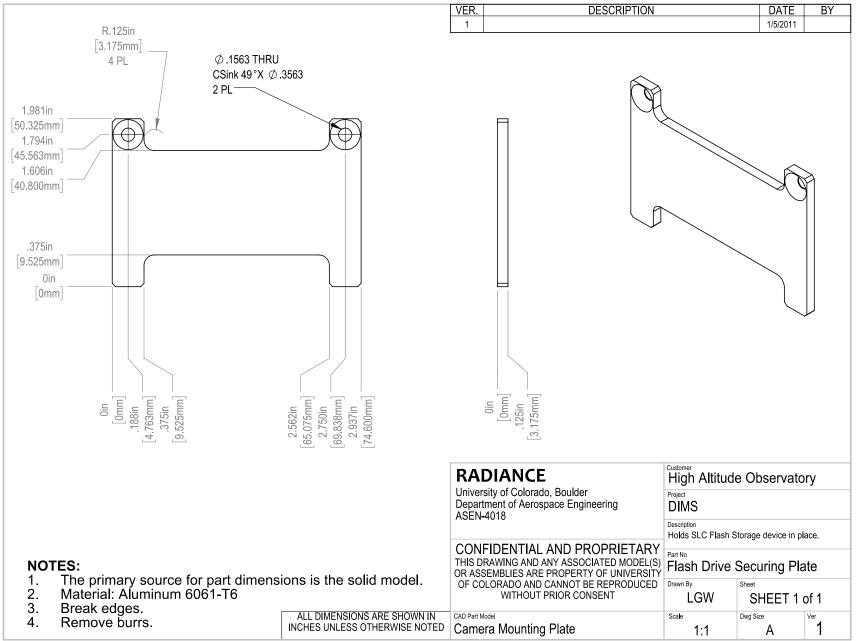


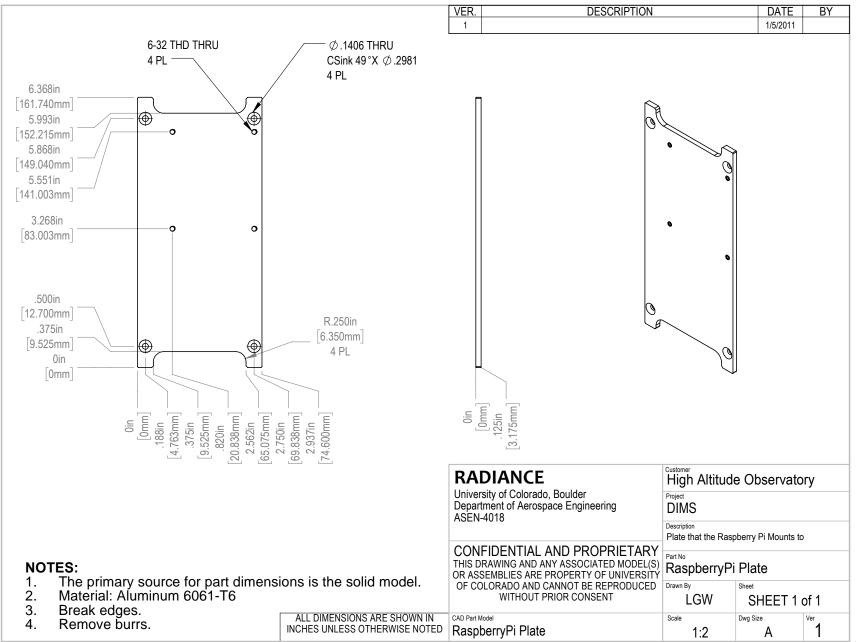


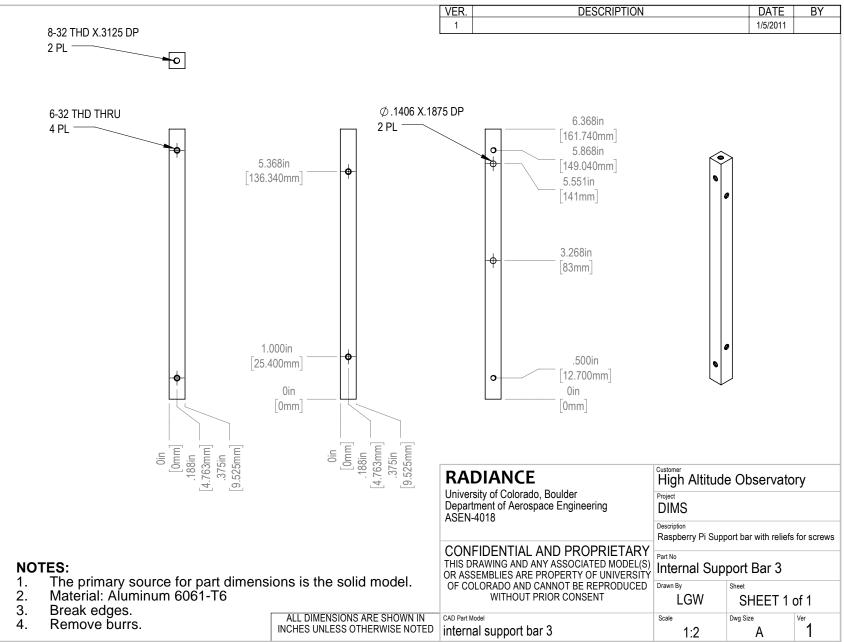


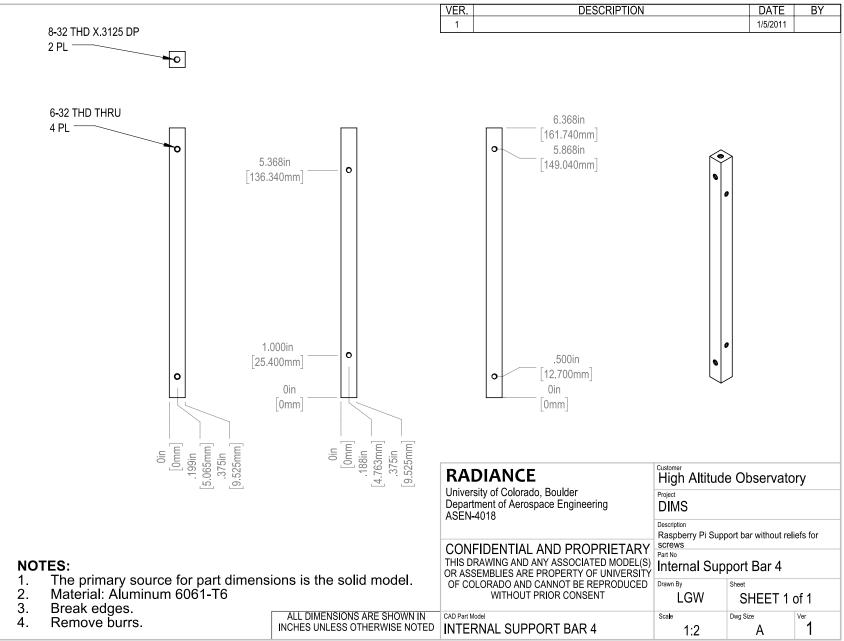












		VER. 1	DESCRIPTION		DATE 1/5/2011	BY
.500in [12.700mm] .315in [8mm] .250in [6.350mm] .187in [4.760mm] 0in [0mm] Umuno U	Ø.1406 THRU HRU CSink 49°X Ø.3406 2 PL (uig21): 3.105(in) (uig21): 88.888mm) (uig21): (uig21)	[93.650mm] [93.650mm] [0mm] [0mm]	[3.175mm]		Ø	
		RADIANCE University of Colorado, Bo			e Observato	ry
NOTES:		CONFIDENTIAL AND PROPRIETARY		Project DIMS Description		
				Lower plate that holds the spectrometer in place.		
		THIS DRAWING AND ANY ASSOCIATED MODEL(S) OR ASSEMBLIES ARE PROPERTY OF UNIVERSITY	Y Lower Opectronneter r lates		tes	
 The primary source for part dimensi Material: Aluminum 6061-T6 Break edges. 		OF COLORADO AND CANNOT BE REPRODUCED WITHOUT PRIOR CONSENT		Drawn By LGW	SHEET 1 C	of 1
4. Remove burrs.	ALL DIMENSIONS ARE SHOWN IN INCHES UNLESS OTHERWISE NOTED	CAD Part Model		Scale 1:1	Dwg Size	Ver

